
Week 8

Memory and Memory Interfacing

Semiconductor Memory Fundamentals

- In the design of all computers, semiconductor memories are used as primary storage for data and code.
- They are connected directly to the CPU and they are the memory that the CPU asks for information (code or data)
- Among the most widely used are RAM and ROM
- **Memory Capacity**
 - The number of bits that a semiconductor memory chip can store is called its chip capacity (bits or bytes)
- **Memory Organization**
 - Each memory chip contains 2^x locations where x is the number of address pins on the chip
 - Each location contains y bits, where y is the number of data pins on the chip
 - The entire chip will contain $2^x * y$ bits
 - Ex. Memory organization of 4K x 4: $2^{12} = 4096$ locations, each location holding 4 bits
- **Memory Speed** (access time)

Memory

- Each memory device has at least one **chip select (CS)** or **chip enable (CE)** or **select (S)** pin that enables the memory device.
 - This enables read and/or write operations.
- Each memory device has at least one **control** pin.
 - For ROMs, an **output enable (OE)** or **gate (G)** is present. The OE pin enables and disables a set of tristate buffers.
 - For RAMs, a **read-write (R/W)** or **write enable (WE)** and **read enable (OE)** are present

Memory Types

•ROM (Read Only Memory)

❖ ROM is the type of memory that does not lose its contents when power is turned off. It is also called **nonvolatile** memory.

❖ PROM (Programmable Memory)

➤ User programmable (one-time programmable) memory

➤ If the information burned into PROM is wrong, it needs to be discarded since internal fuses are blown permanently.

➤ Special equipment needed: ROM burner or ROM programmer

❖ EPROM (Erasable Programmable ROM) 2,000 times

➤ Allows making changes in the contents of PROM after it is burned

➤ One can program the memory chip and erase it thousands of times

➤ Erasing its contents can take up to 20 minutes; the entire chip is erased

➤ All EPROM chips have a window that is used to shine ultraviolet (UV) radiation to erase its contents

➤ Also referred to as UV-EPROM

Memory Types

❖ EEPROM (Electrically Erasable ROM) 500,000 times

- Method of erasure is electrical
- Moreover, one can select which byte to be erased
- Cost per bit is much higher than for UV-EPROM

❖ Flash Memory EPROM

- First, the process of erasure of the entire contents takes less than a second, or one might say in a flash, hence its name: flash memory
- When flash memory's contents are erased, the entire device is erased.
- Even though flash memories are writeable, like EPROMs they find their widest use in microcomputer systems for storage of firmware

❖ RAM (Random Access Memory) infinite times

- RAM memory is called volatile memory since cutting off the power to the IC will mean the loss of data.
- Also referred to as R/WM (Read And Write Memory)

Minmode 8088 Microcomputer system memory circuitry

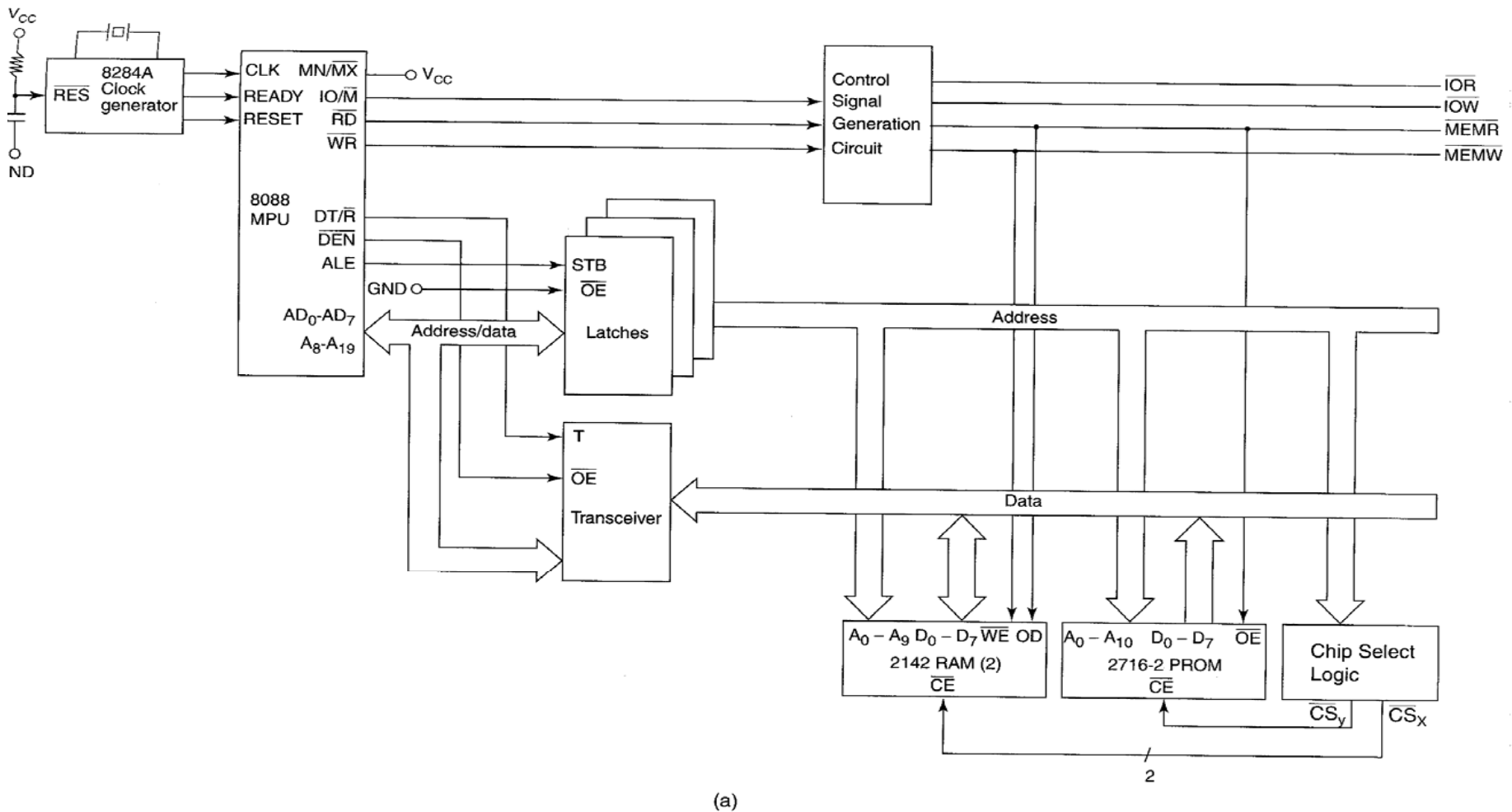
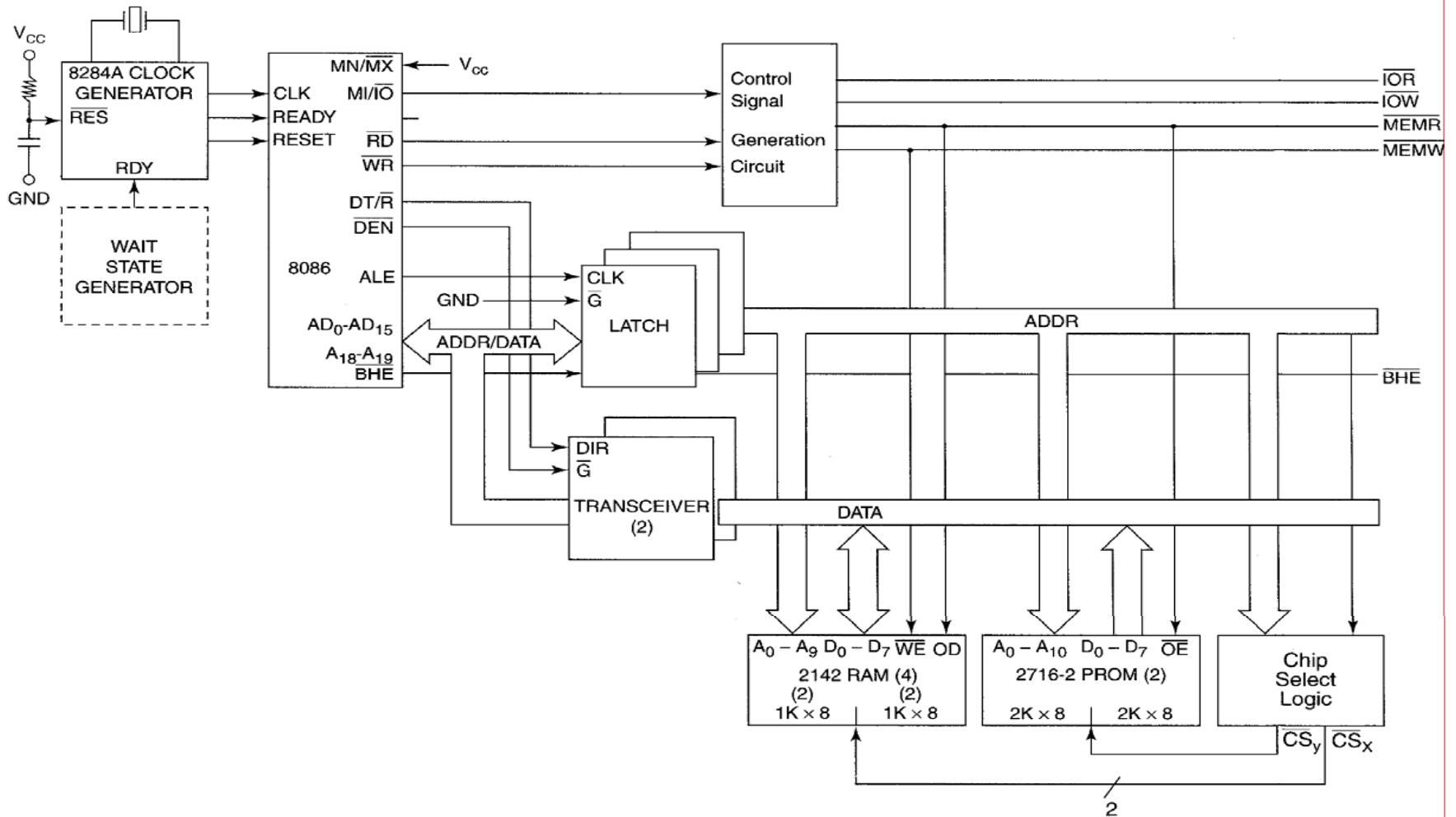


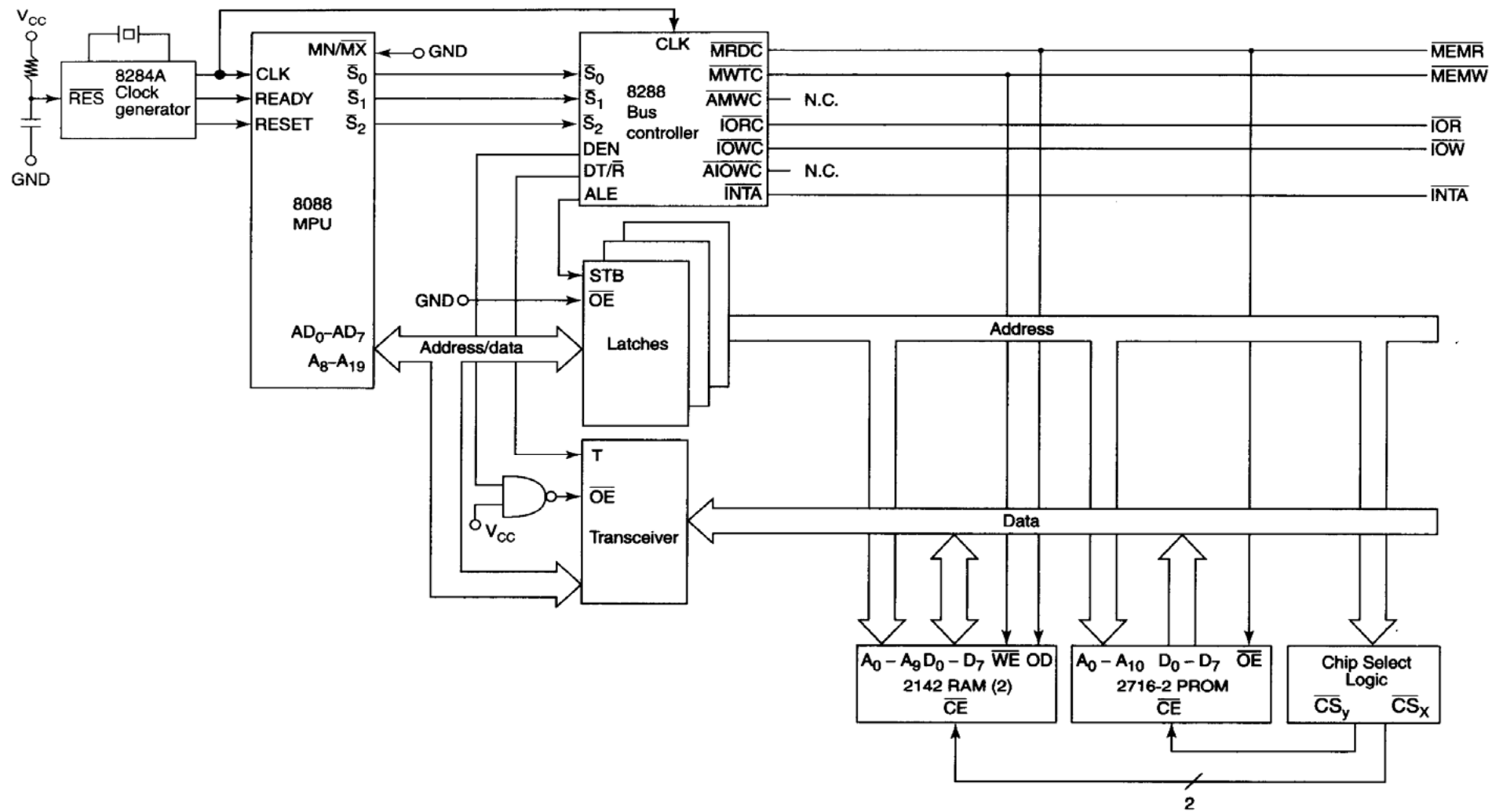
Figure 9-37 (a) Minimum-mode 8088 system memory interface. (Reprinted with permission of Intel Corporation, Copyright/Intel Corp. 1981) (b) Minimum-mode 8086 system memory interface. (Reprinted with permission of Intel Corporation, Copyright/Intel Corp. 1979) (c) Maximum-mode 8088 system memory interface. (Reprinted with permission of Intel Corporation, Copyright/Intel Corp. 1981)

Minmode 8086 Microcomputer system memory circuitry



(b)

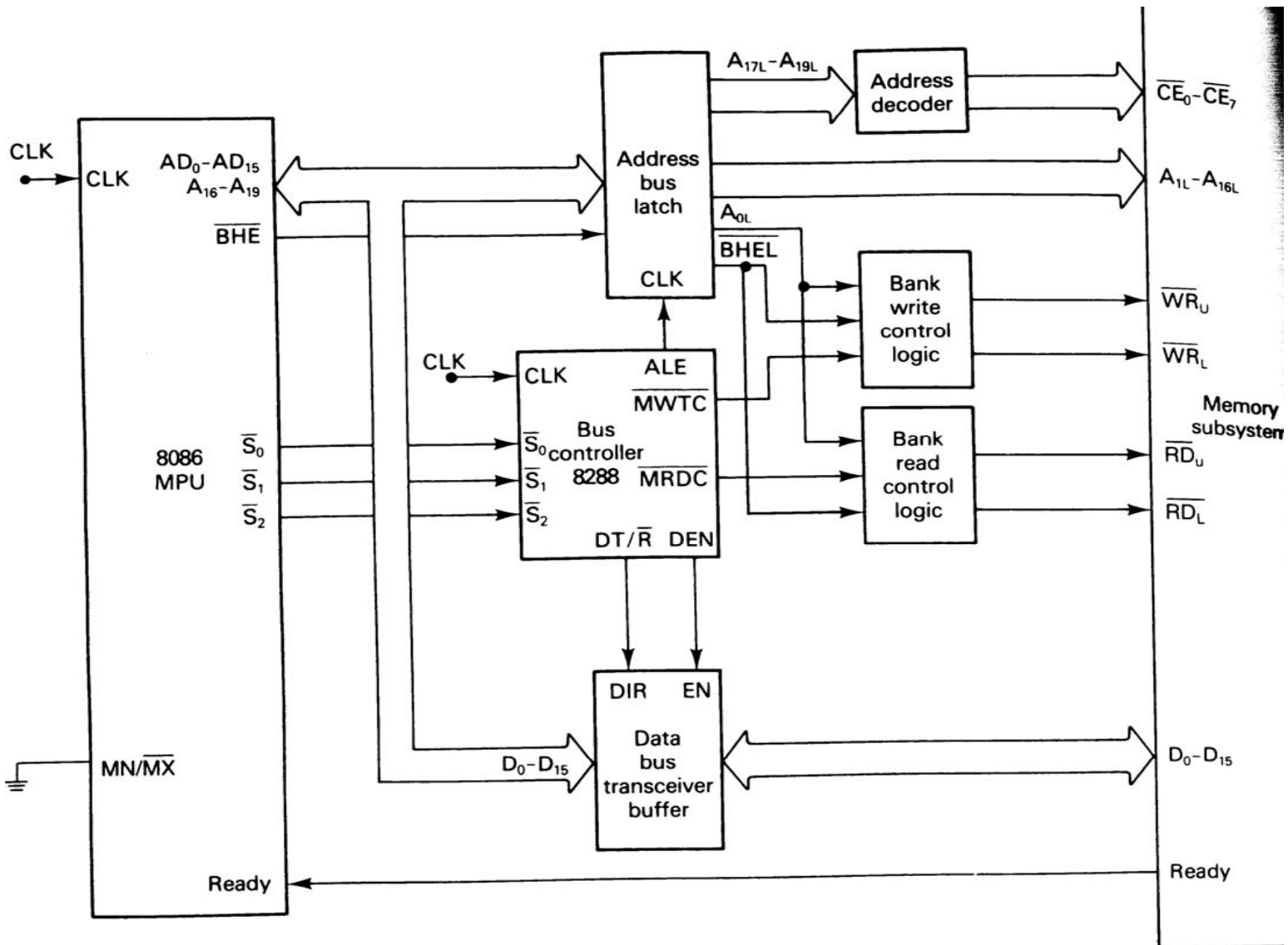
Maxmode 8088 Microcomputer system memory circuitry



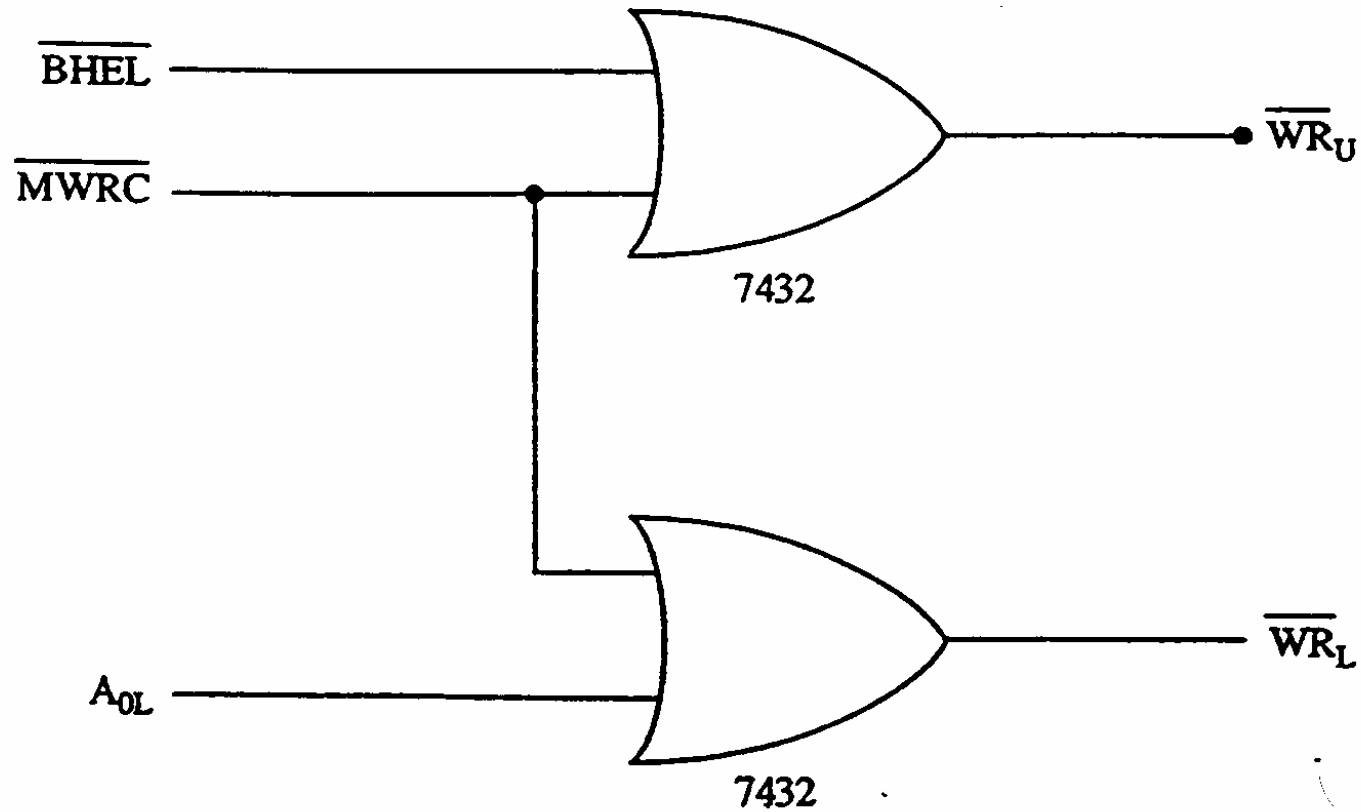
(c)

Figure 9-37 (continued)

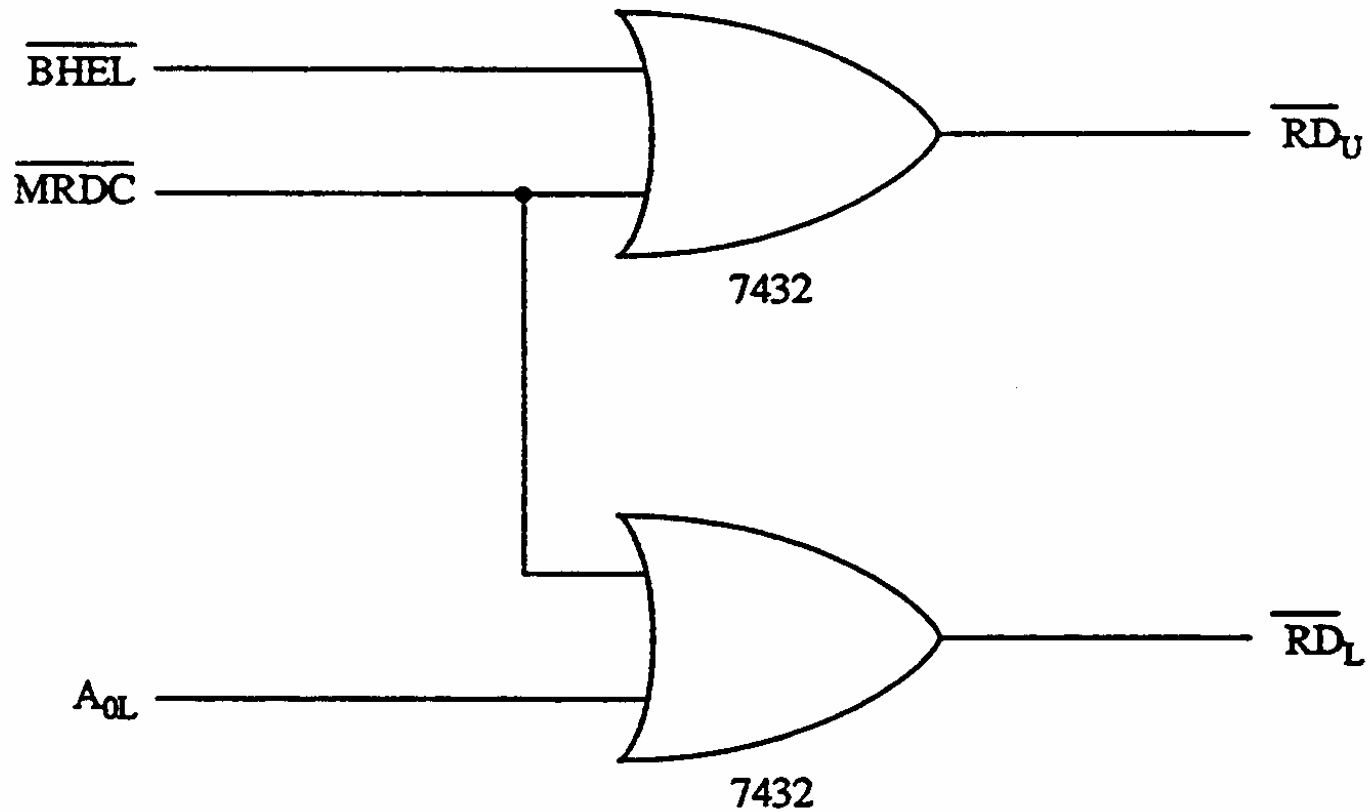
Memory Interface



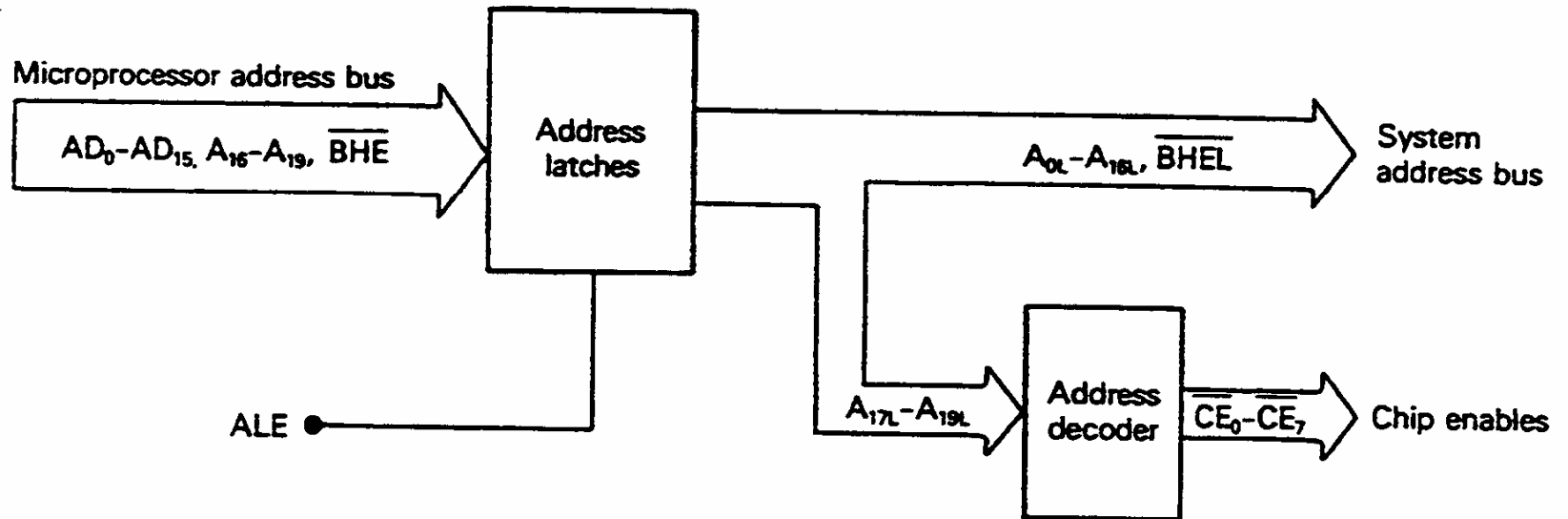
Bank Write Control Logic



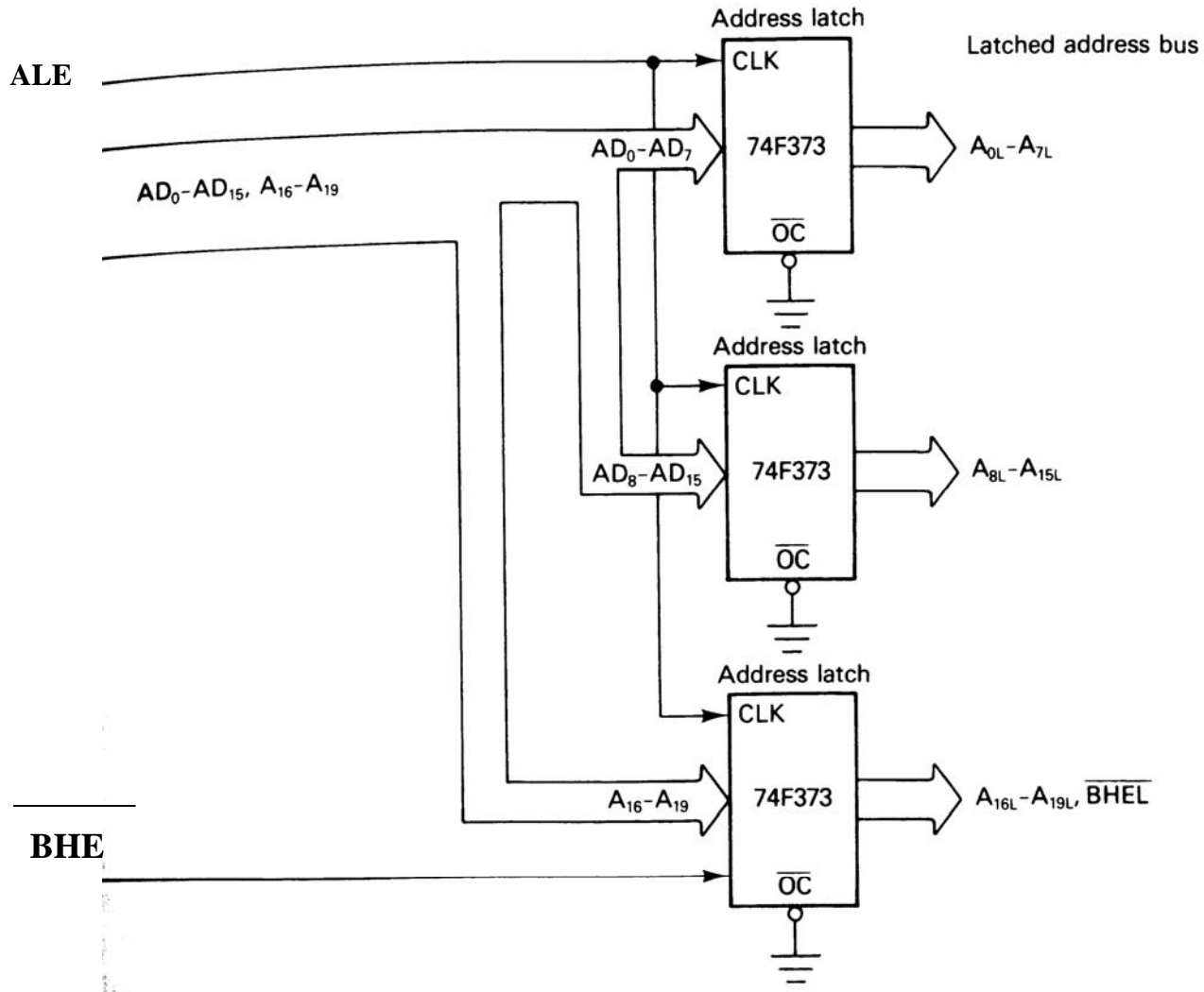
Bank Read Control Logic



Address Bus Configuration with Address Decoding

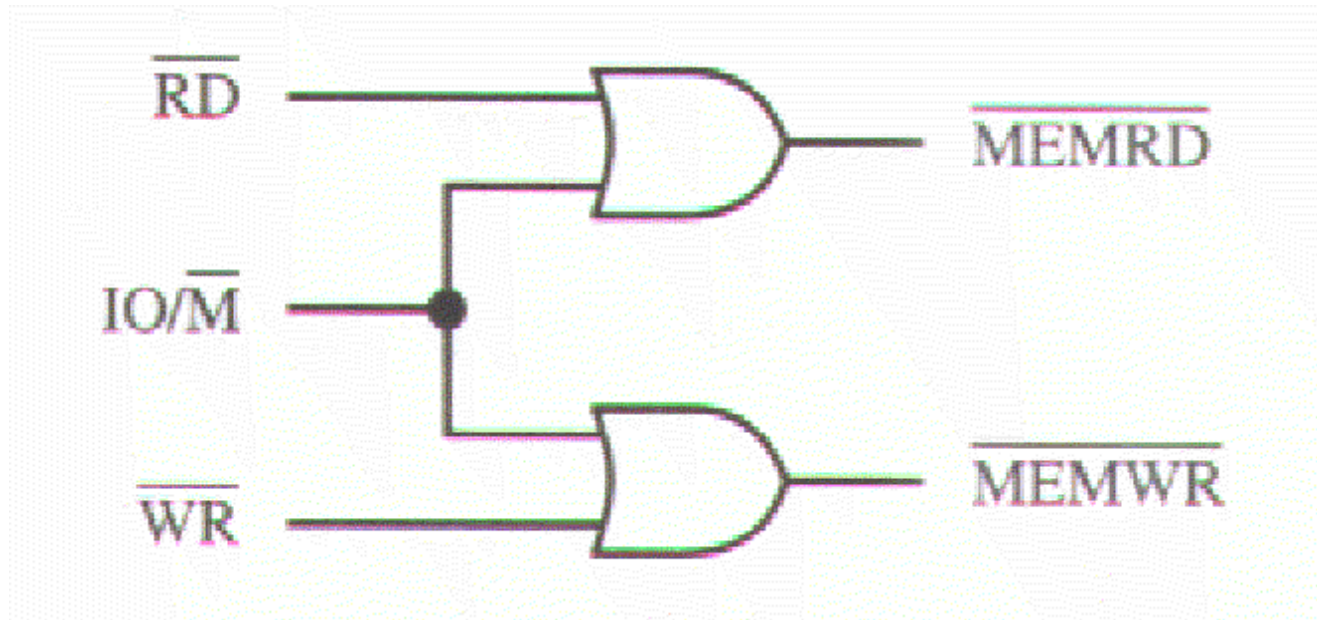


Address Latch Circuit



Generation of MEMRD & MEMWR in Minmode

Control Signal Generation Circuit



8088 Memory and I/O address spaces

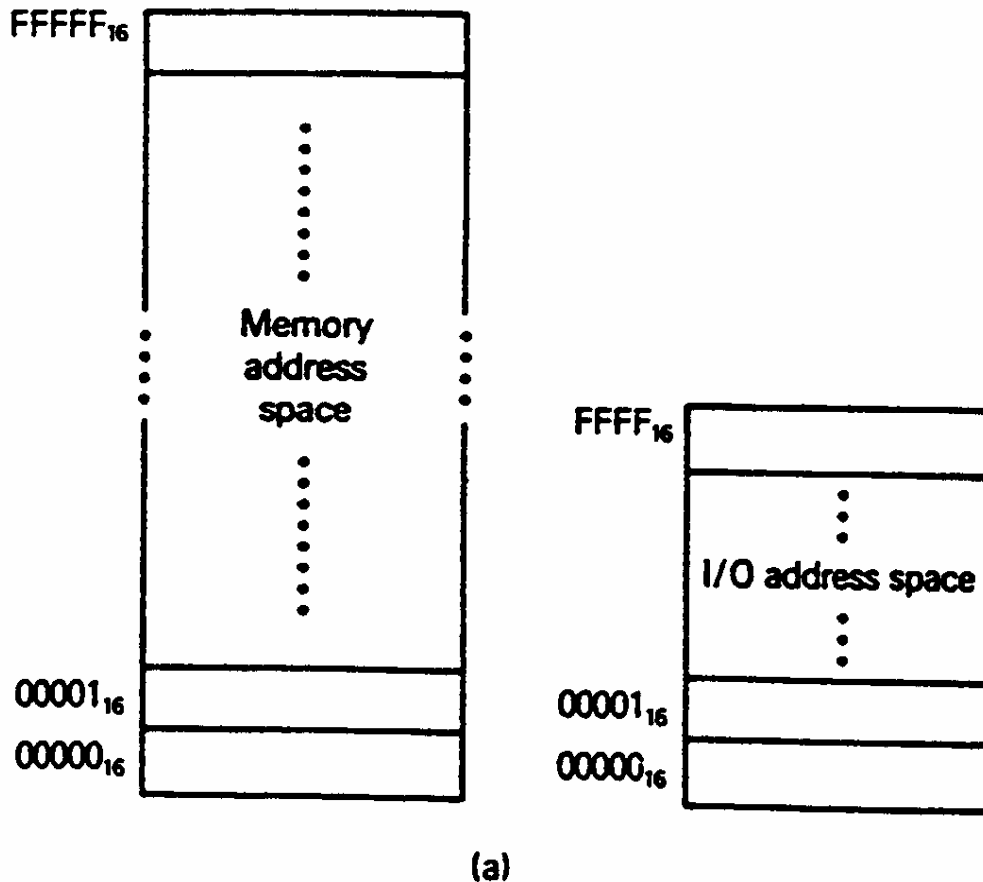
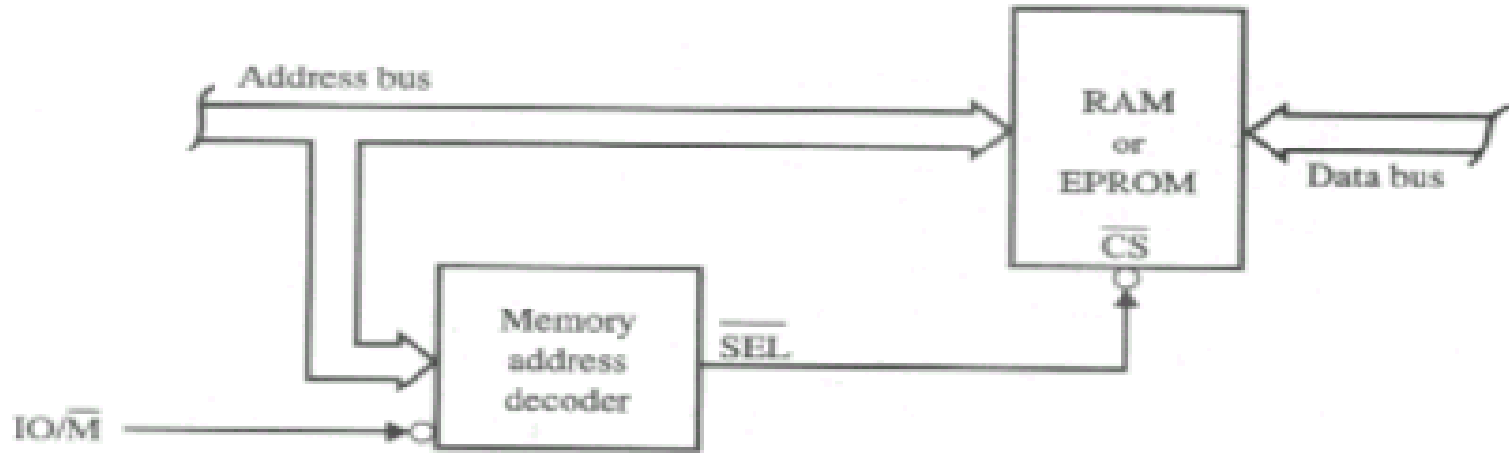


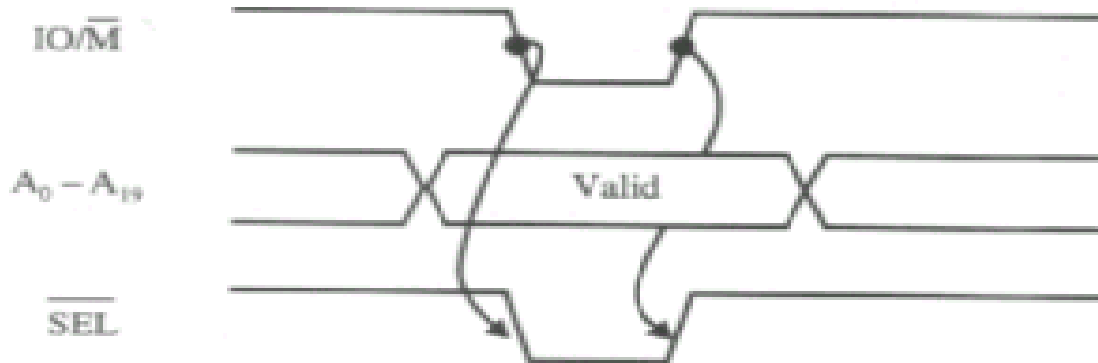
Figure 8-46 8088/8086 memory and I/O address spaces.

We first look at the memory addressing

Address Selection

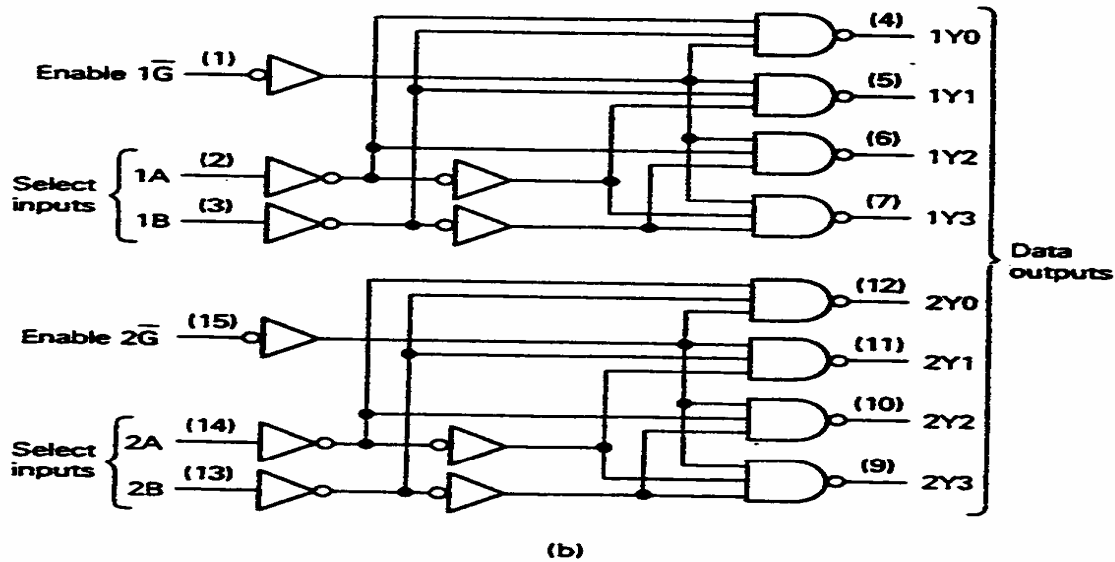
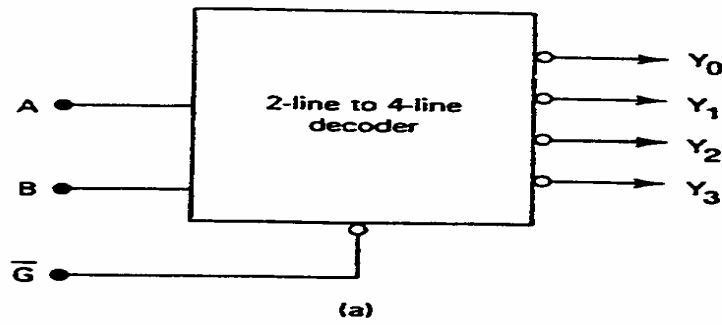


(a)



(b)

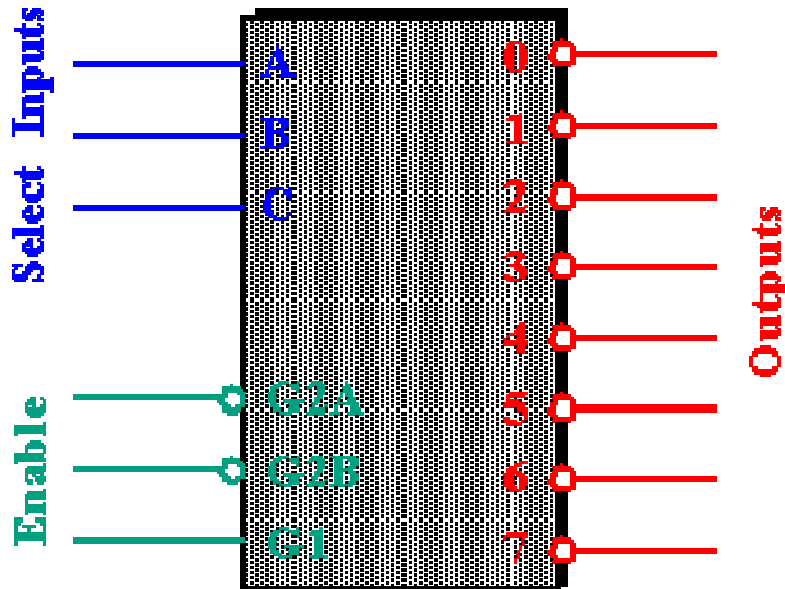
74F139 2-line to 4-line decoder



INPUTS			OUTPUTS			
ENABLE	SELECT		Y0	Y1	Y2	Y3
\bar{G}	B	A				
H	X	X	H	H	H	H
L	L	L	L	H	H	H
L	L	H	H	L	H	H
L	H	L	H	H	L	H
L	H	H	H	H	H	L

(c)

Memory Address Decoding



3-8 Decoder
(for example: 74LS138)

Inputs						Output							
Enable			Select										
G2A	G2B	G1	C	B	A	0	1	2	3	4	5	6	7
1	X	X	X	X	X	1	1	1	1	1	1	1	1
X	1	X	X	X	X	1	1	1	1	1	1	1	1
X	X	0	X	X	X	1	1	1	1	1	1	1	1
0	0	1	0	0	0	0	1	1	1	1	1	1	1
0	0	1	0	0	1	1	0	1	1	1	1	1	1
0	0	1	0	1	0	1	1	0	1	1	1	1	1
0	0	1	0	1	1	1	1	1	0	1	1	1	1
0	0	1	1	0	0	1	1	1	1	0	1	1	1
0	0	1	1	0	1	1	1	1	1	1	0	1	1
0	0	1	1	1	0	1	1	1	1	1	1	0	1
0	0	1	1	1	1	1	1	1	1	1	1	1	0

Address Decoder Circuit

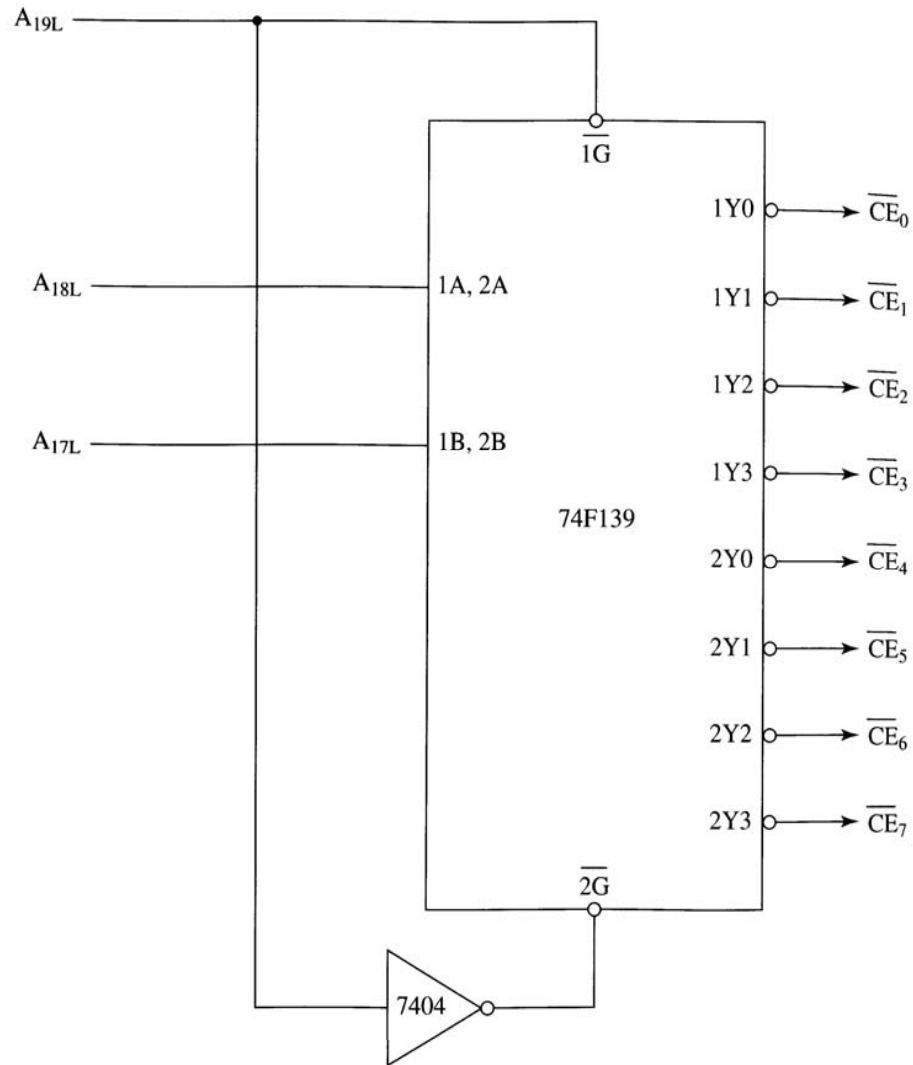


Figure 8–35 Address decoder circuit

Example on Address Decoding

A circuit containing 32KB of RAM is to be interfaced to an 8088 based system, so that the first address of the RAM is at 48000H. What is the entire range of the RAM Address? How is the address bus used to enable the RAMs? What address lines should be used?

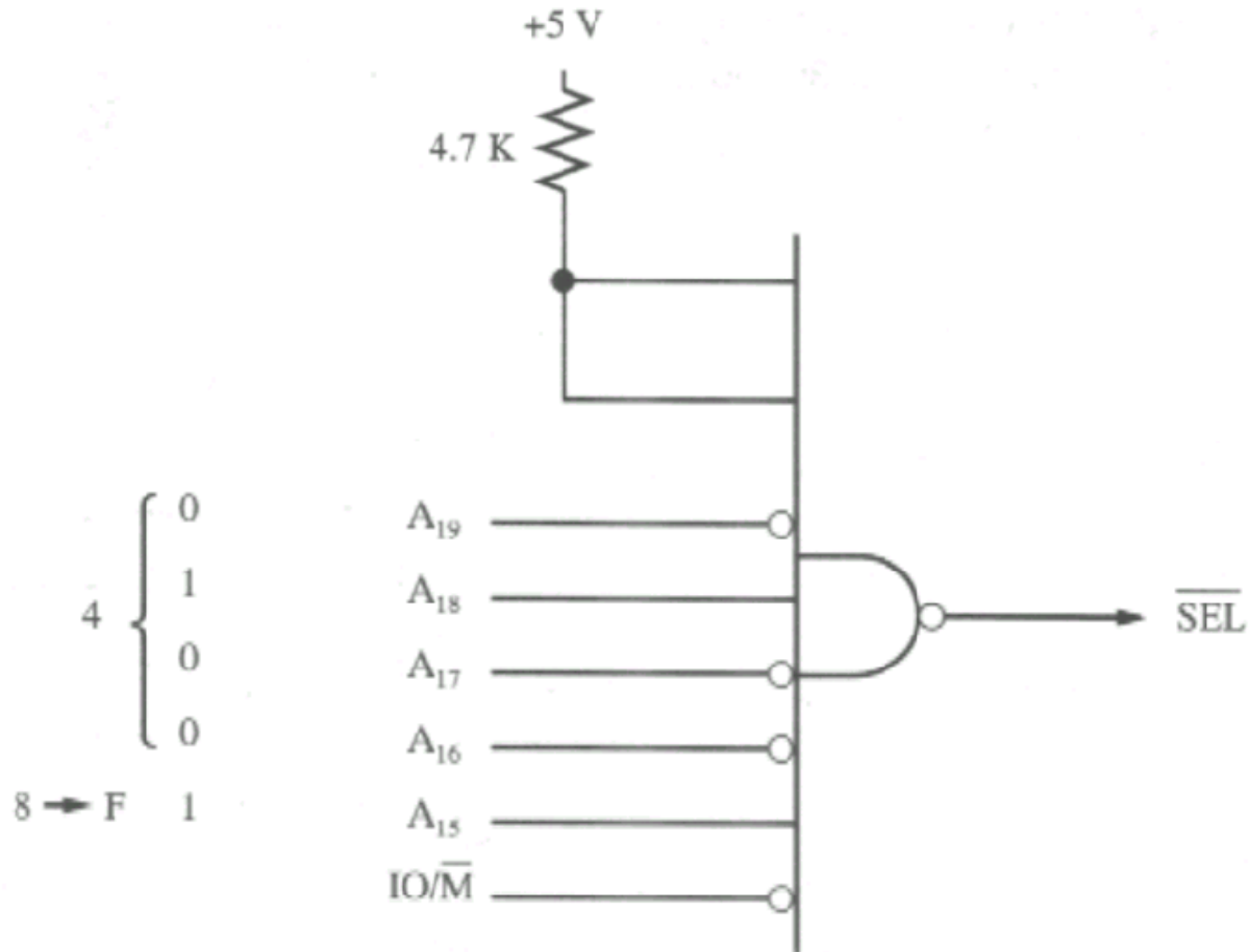
4	8 → F	0 → F	0 → F	0 → F
A ₁₉ A ₁₈ A ₁₇ A ₁₆	A ₁₅ A ₁₄ A ₁₃ A ₁₂	A ₁₁ A ₁₀ A ₉ A ₈	A ₇ A ₆ A ₅ A ₄	A ₃ A ₂ A ₁ A ₀
0 1 0 0	1 X X X	X X X X	X X X X	X X X X

X— Don't care (Use 0 or 1)

These 5 address lines set the base address of the memory.

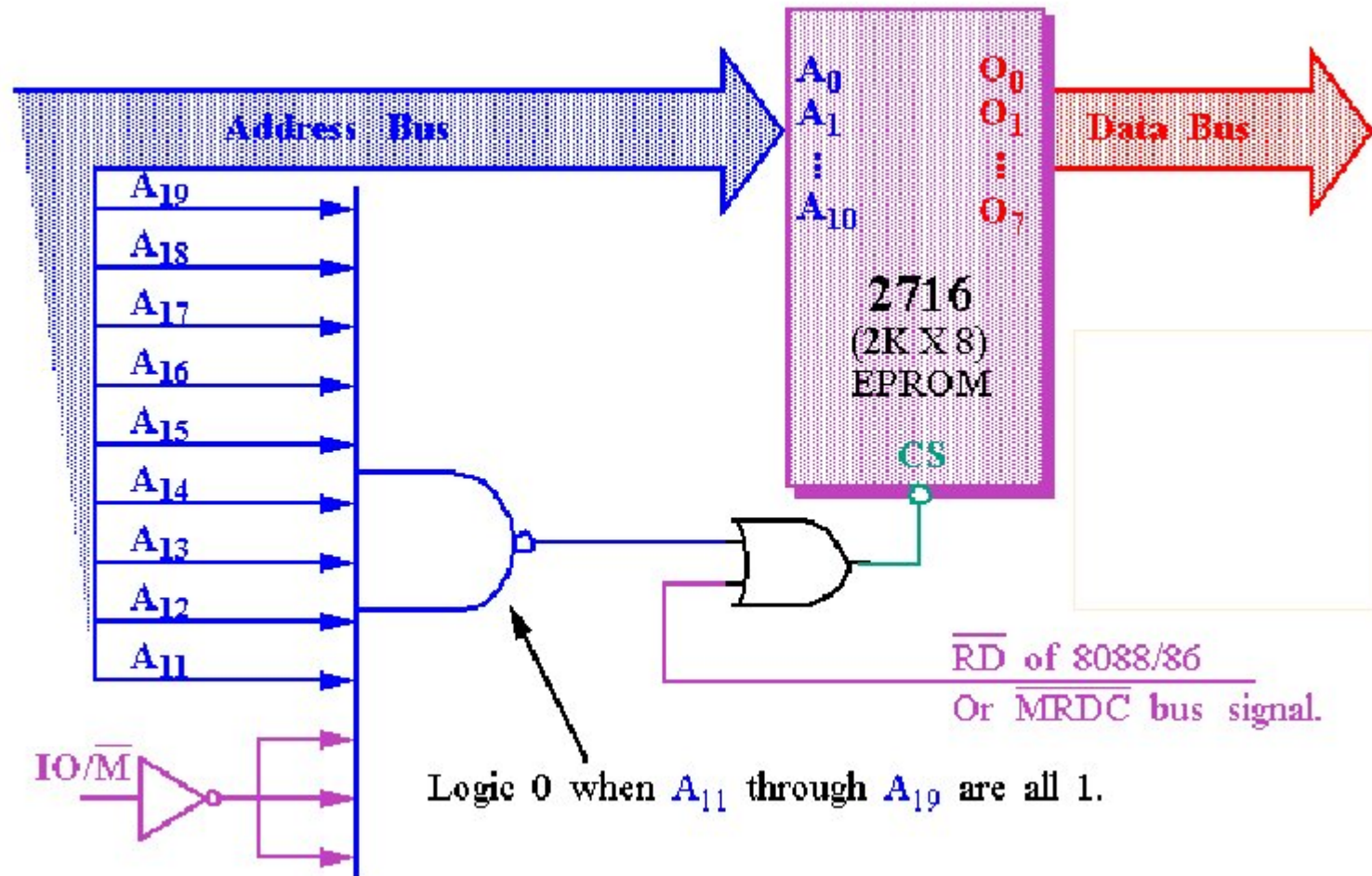
These 15 address lines will select one of 2^{15} (or 32,768) locations inside the RAMs.

Example on Address Decoding

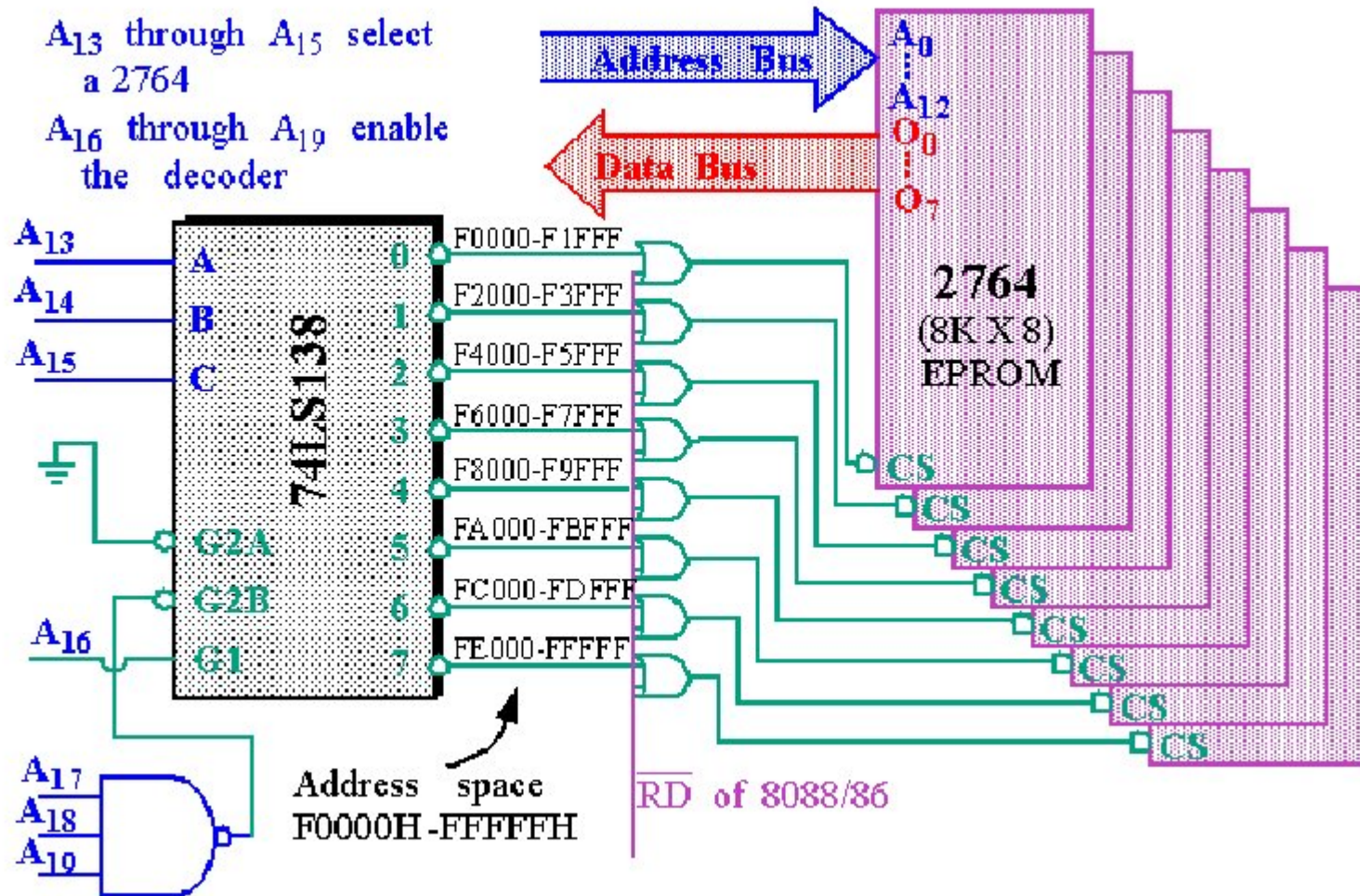


Memory Address Decoder for 48000 to 4FFFF Range

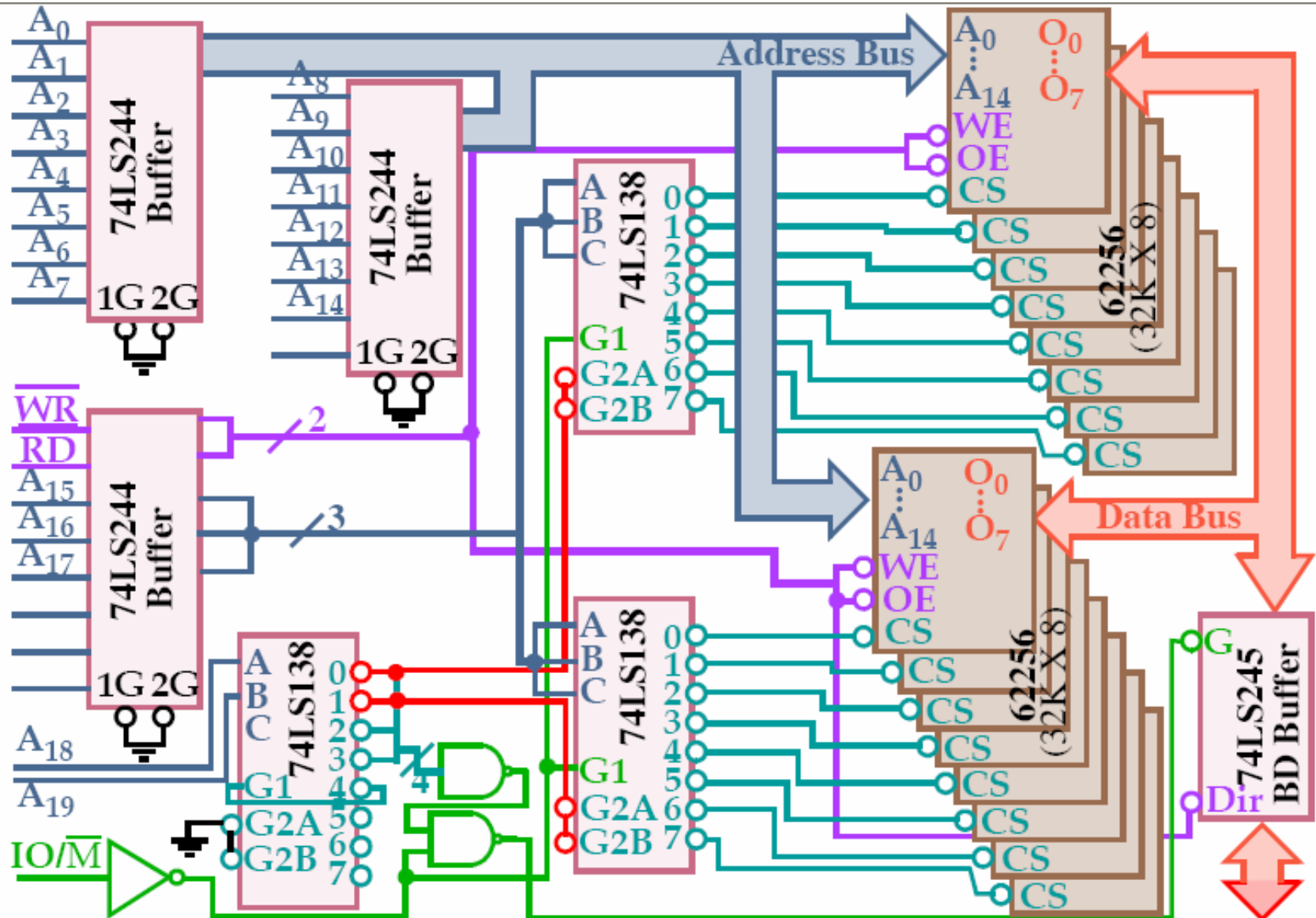
Memory Address Decoding



Memory Address Decoding

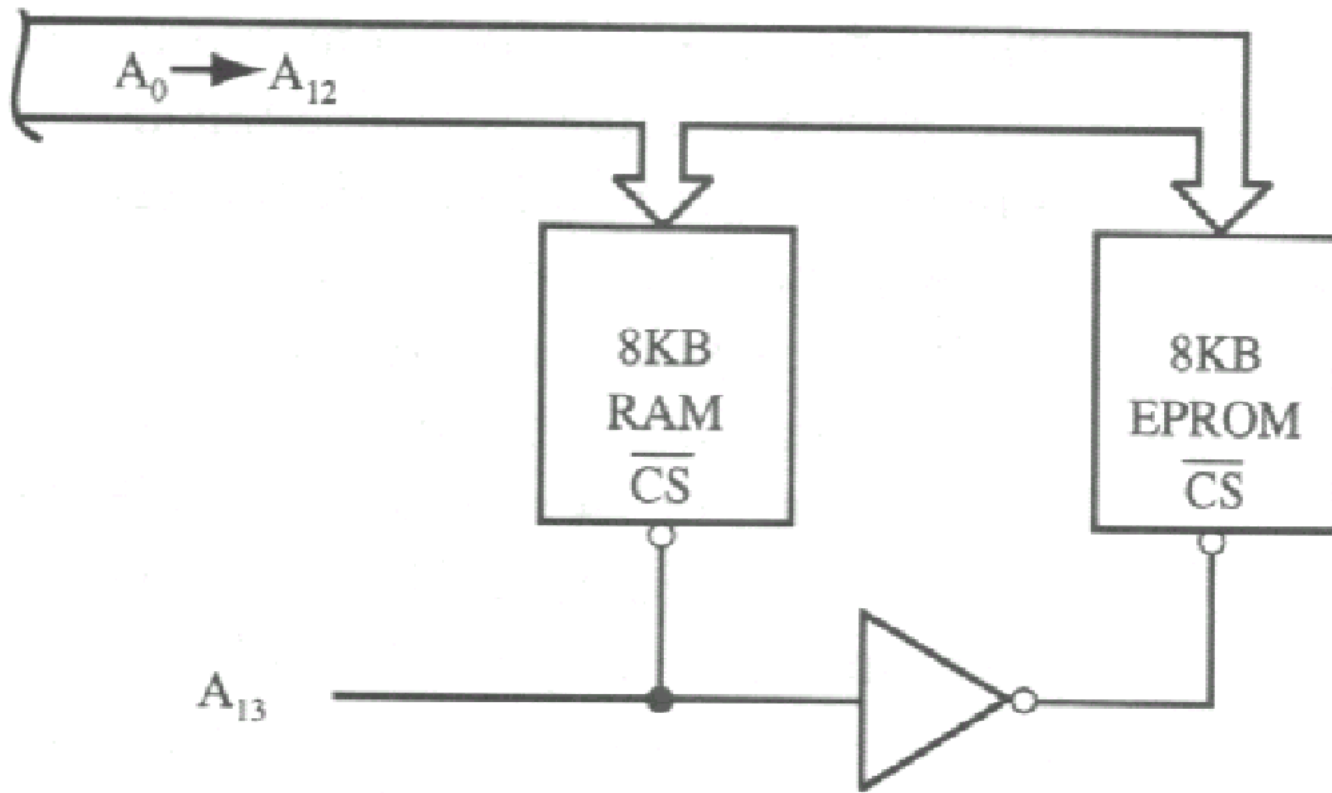


Memory Addressing



Partial Address Decoding

- Not all the address lines need to be used. (A14-A19 not used).
So FFFF0, 3BFF0, 07FF0 or C3FF0 get the same data.
- (+) The purpose is get the job done in minimum hardware.
- (-) Feature expansion of the memory is impossible, and may cause invalid data reads due to overlapping memory segment reads (a fatal error)

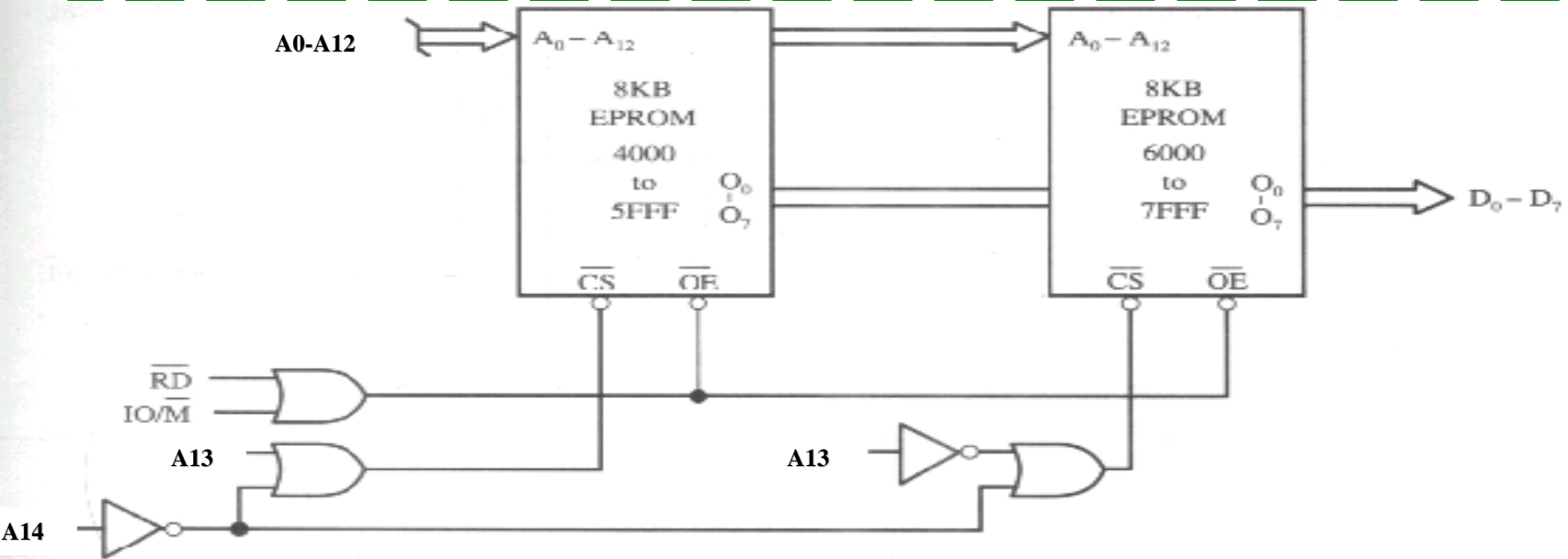


Partial Address Decoding

A_{19}	A_{18}	A_{17}	A_{16}	A_{15}	A_{14}	A_{13}	A_{12}	A_{11}	A_{10}	A_9	A_8	A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0
0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0	0	0	0	0	1	0	1	1	1	1	1	1	1	1	1	1	1	1	1
0	0	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0
0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1

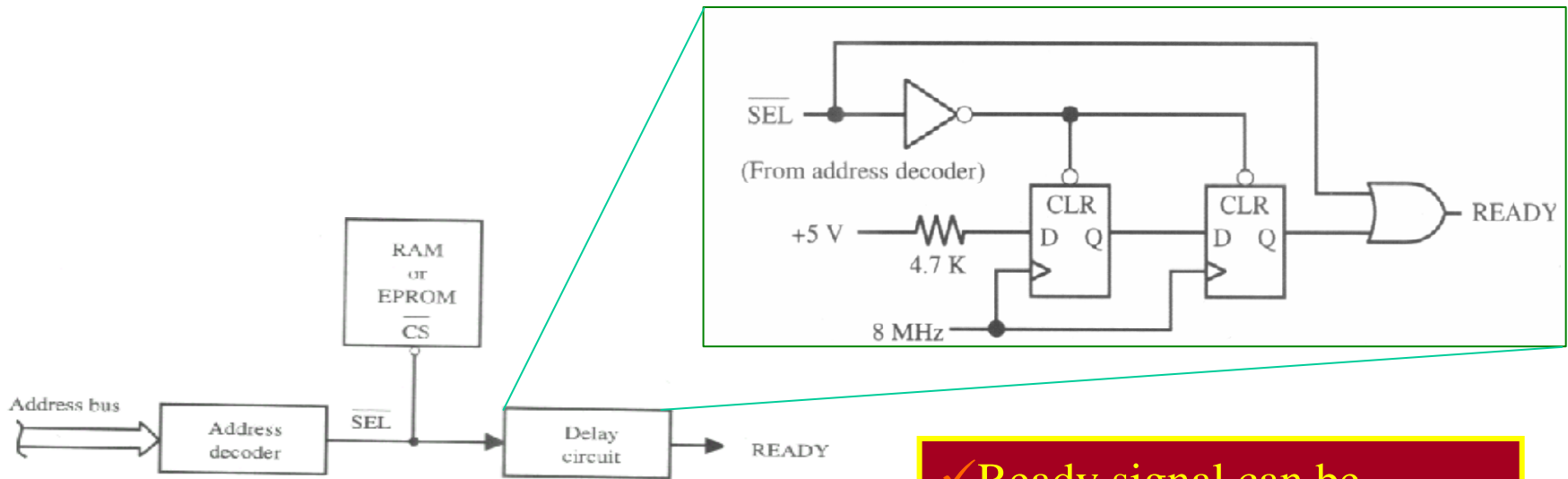
For DECODER
To EPROM

Foldback memory exists

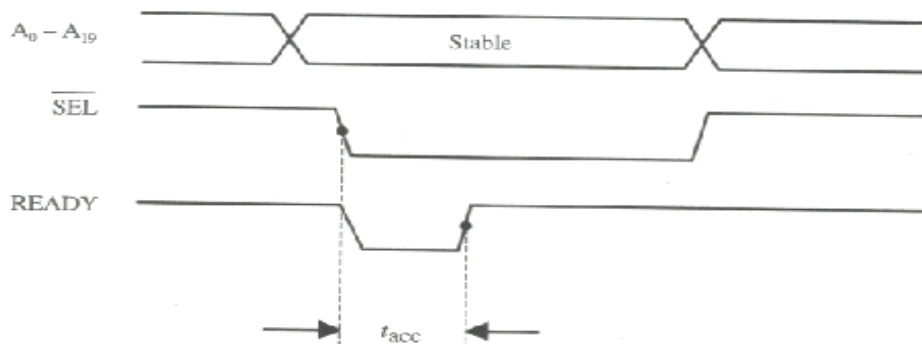


(b)

Generating Wait States in Hardware



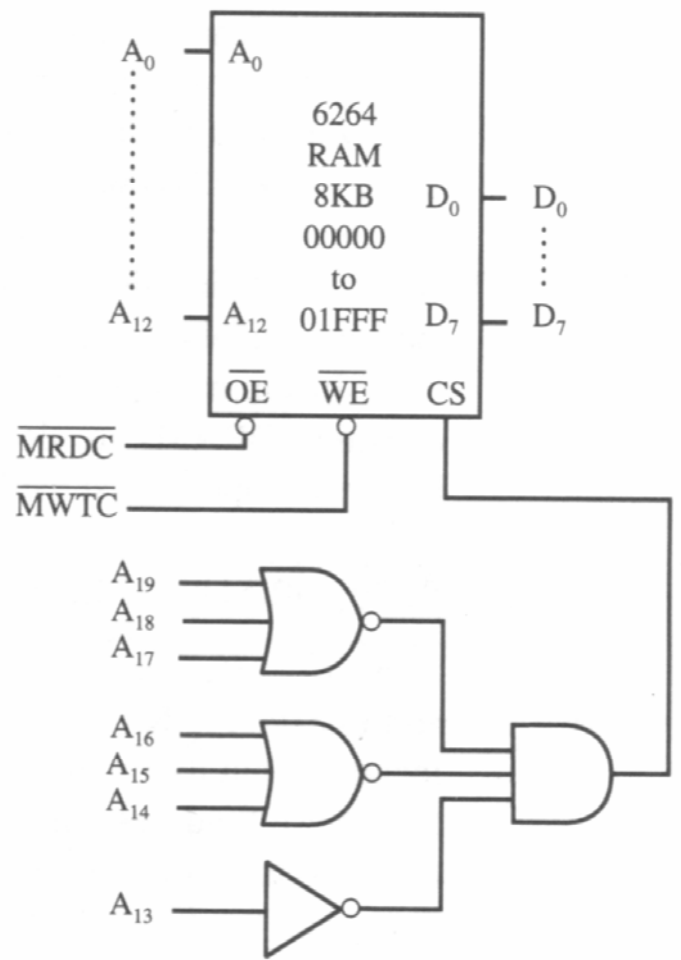
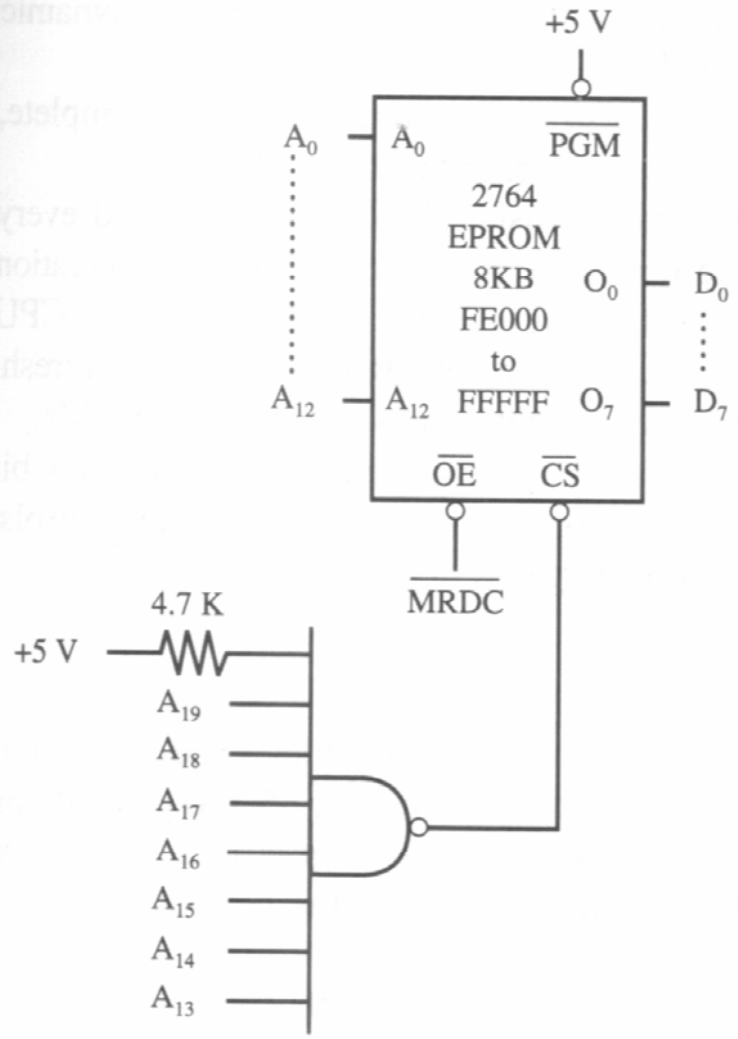
(a)



(b)

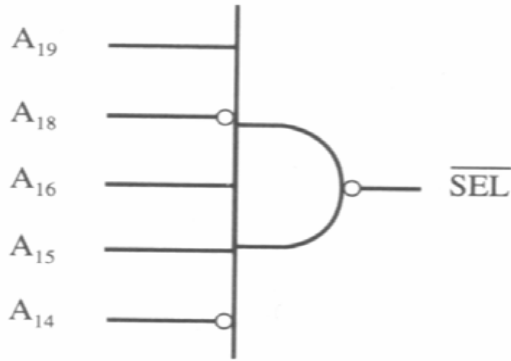
- ✓ Ready signal can be generated by special hardware using the $\overline{\text{SEL}}$ signal from the address decoder.
- ✓ The circuit above will generate two clock periods of zero signal for the READY output.

A complete RAM/EPROM Memory

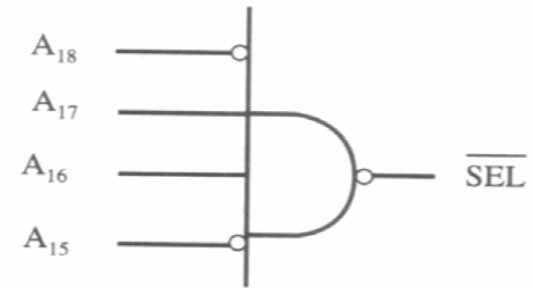


(b)

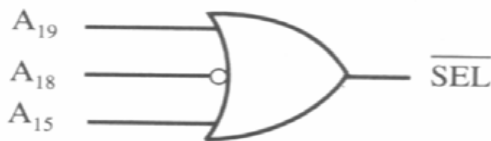
Examples: Find different addressing for CS (A0-A13 used by memories)



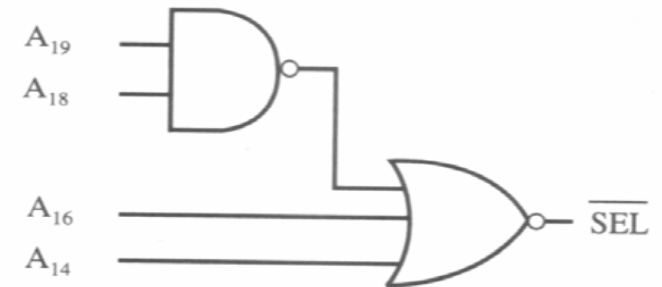
10x1 10/xx xxxx xxxxxxxx



x011 0x/xx xxxx xxxxxxxx



01xx x0/xx xxxx xxxxxxxx

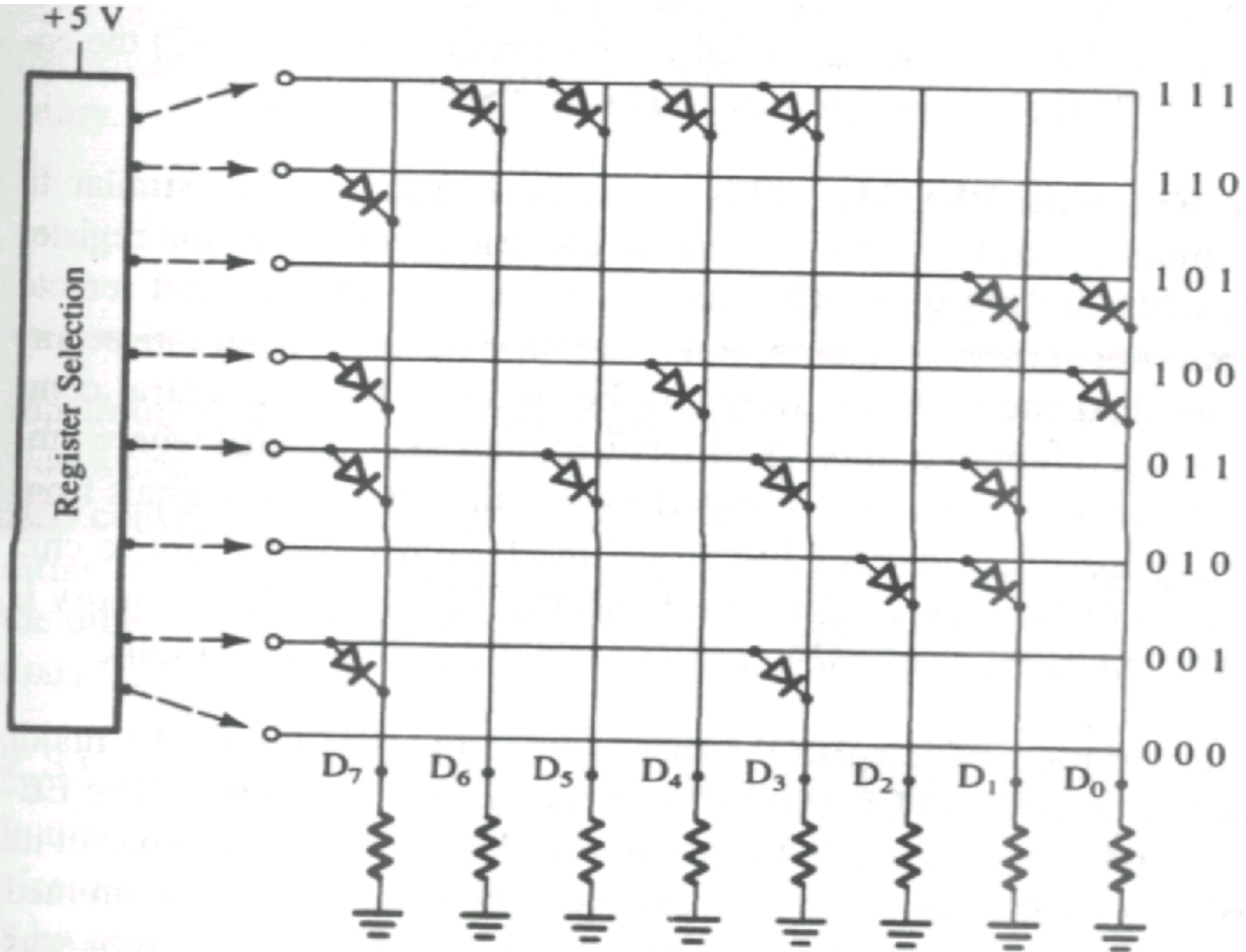


(A19 and A18=0) or A16=1 or A14=1



xx1x xx/xx xxx x xxxxxxxx

ROM



ROM

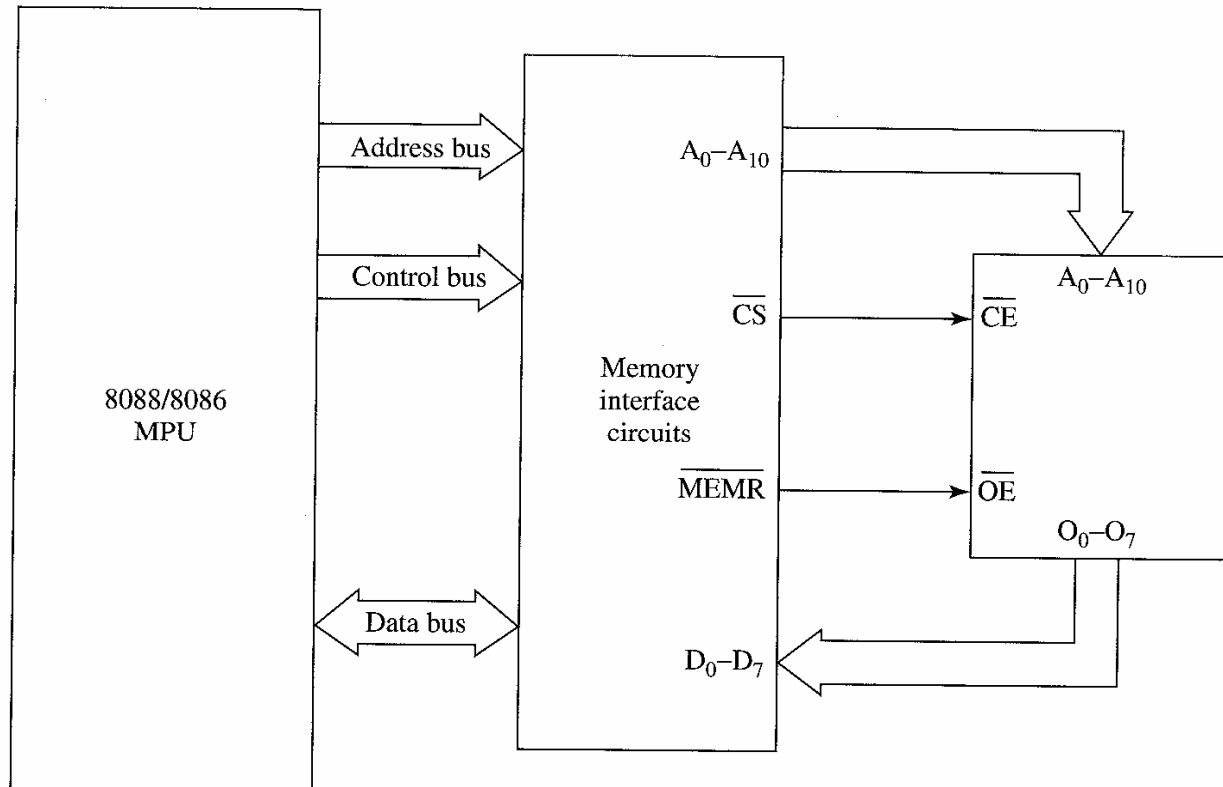
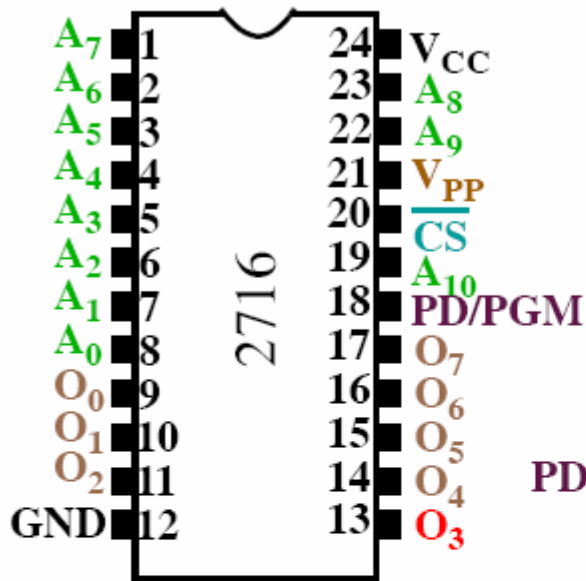


Figure 9-4 Read-only memory interface.

EPROM

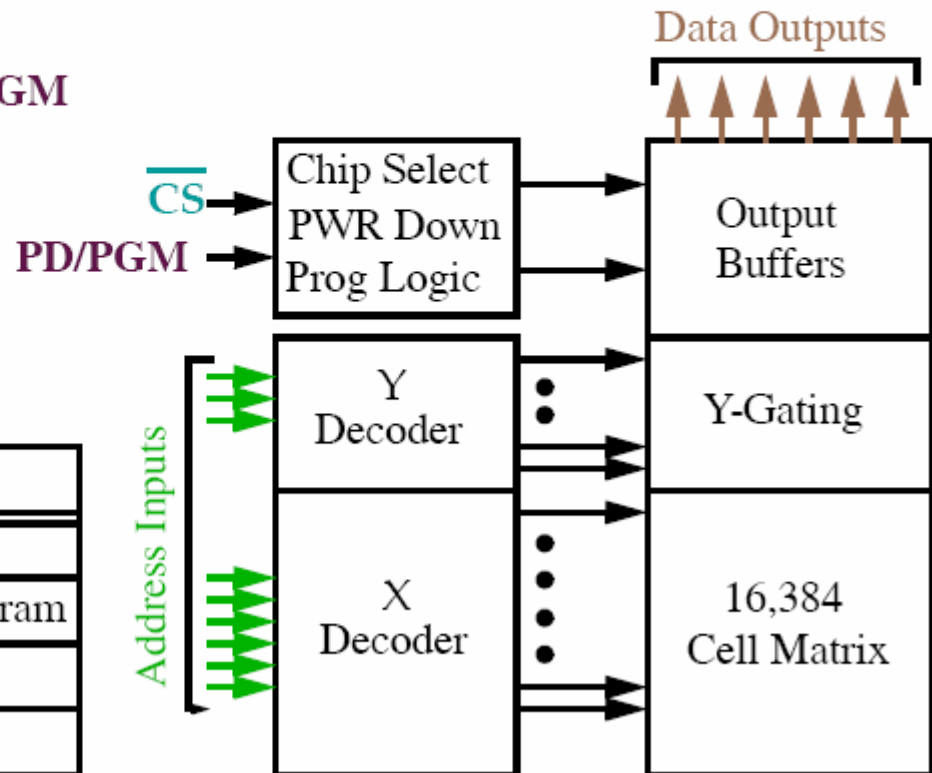
Intel 2716 EPROM (2K X 8):



2K x 8 EPROM

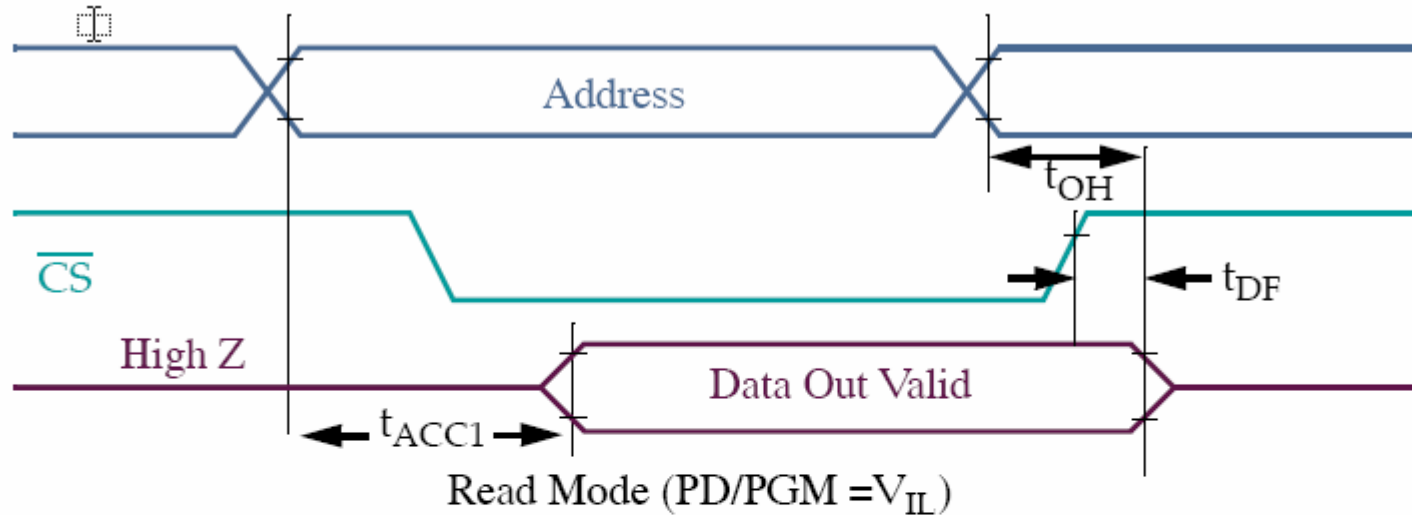
Pin(s)	Function
A_0 - A_{10}	Address
PD/PGM	Power down/Program
\overline{CS}	Chip Select
O_0 - O_7	Outputs

V_{PP} is used to program the device by applying 25V and pulsing PGM while holding \overline{CS} high.



EPROM Critical Timing

2716 Timing diagram:



Sample of the data sheet for the 2716 A.C. Characteristics.

Symbol	Parameter	Limits			Unit	Test Condition
		Min	Typ.	Max		
t_{ACC1}	Addr. to Output Delay		250	450	ns	PD/PGM= \overline{CS} = V _{IL}
t_{OH}	Addr. to Output Hold	0			ns	PD/PGM= \overline{CS} = V _{IL}
t_{DF}	Chip Deselect to Output Float	0		100	ns	PD/PGM= V _{IL}
...

This EPROM would need a READY generation to work with a 8086 with 5Mhz.

RAM types

- **SRAM (Static RAM)**
 - Storage cells are made of flip-flops and therefore they do not require refreshing to keep their data
 - Cells handling one bit requires 6 or 4 transistors each, which is too many
 - SRAMS are widely used for cache memory and battery-backed memory systems.
 - Speeds as fast as 10ns. But limited in size ~256Kx8
- **DRAM (Dynamic RAM)**
 - Uses MOS capacitors to store a bit
 - Requires constant refreshing due to leakage (every 2ms – 4ms)
 - Advantages
 - High density (capacity) ~1GBX8
 - Cheaper cost per bit
 - Lower power consumption
 - Disadvantage
 - While it is being refreshed, data cannot be accessed
 - Larger access times
 - Too many pins due to large size

SRAM

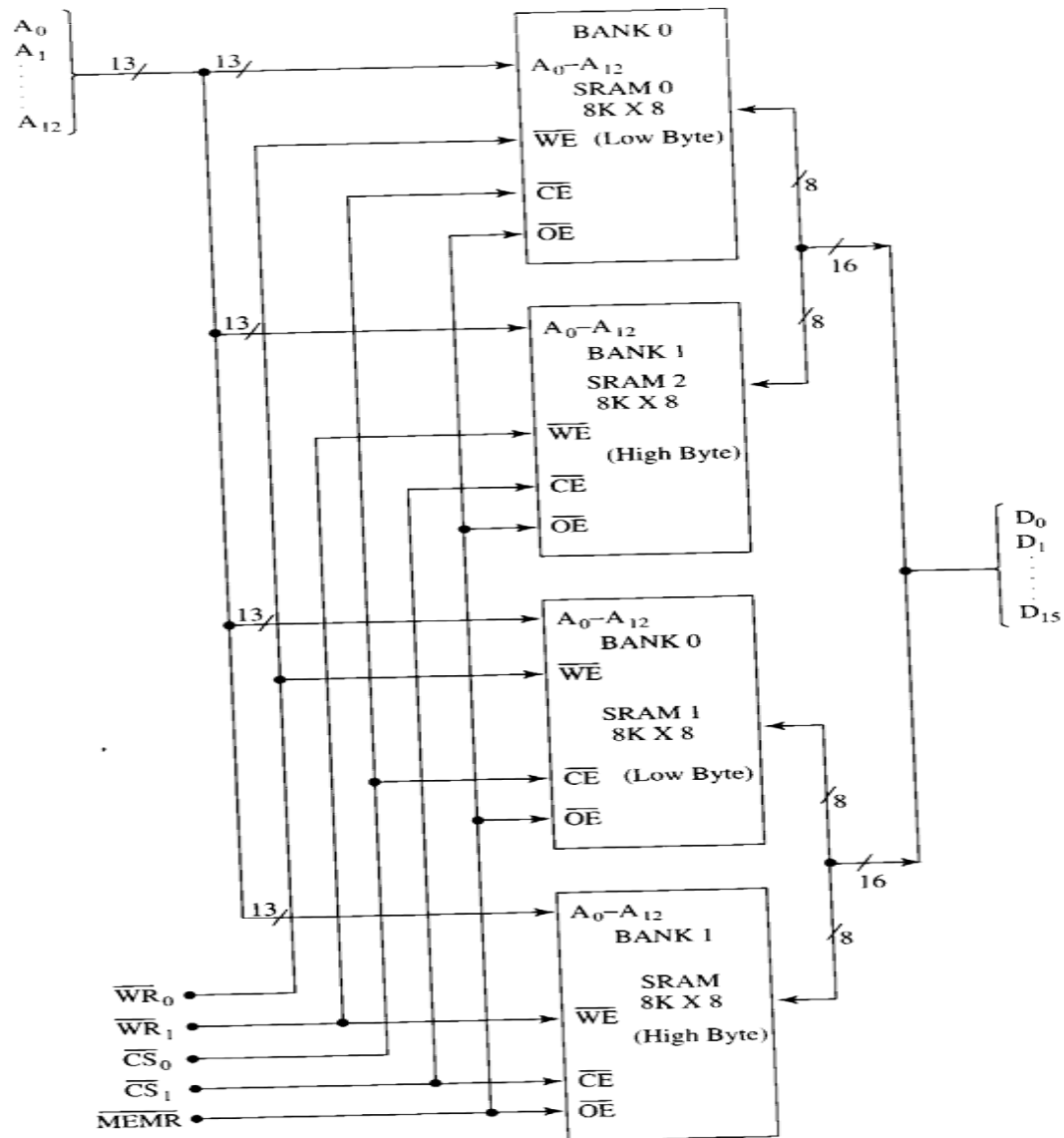


Figure 9-12 16K x 16-bit SRAM circuit.

SRAM

SRAM	Density (bits)	Organization
4361	64K	64K × 1
4363	64K	16K × 4
4364	64K	8K × 8
43254	256K	64K × 4
43256A	256K	32K × 8
431000A	1M	128K × 8

Figure 9-13 devices.

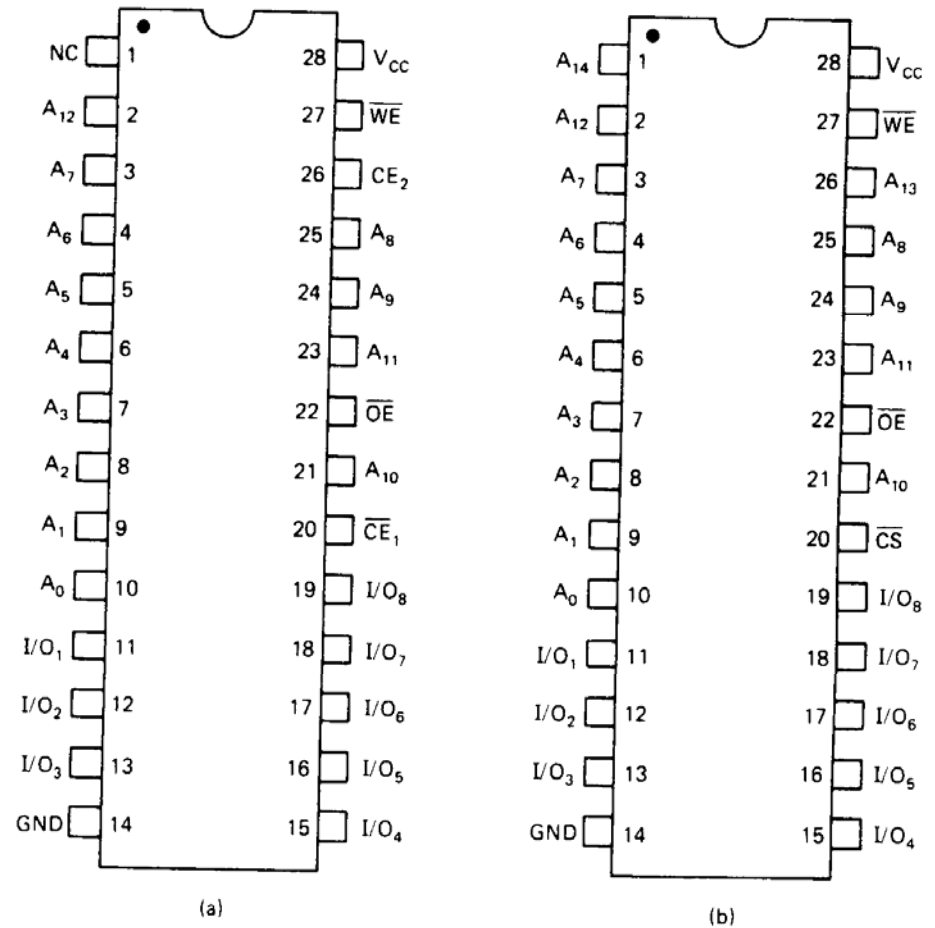


Figure 9-14 (a) 4364 pin layout. (b) 43256A pin layout.

DRAM

DRAM	Density (bits)	Organization
2164B	64K	64K × 1
21256	256K	256K × 1
21464	256K	64K × 4
421000	1M	1M × 1
424256	1M	256K × 4
44100	4M	4M × 1
44400	4M	1M × 4
44160	4M	256K × 16
416800	16M	8M × 2
416400	16M	4M × 4
416160	16M	1M × 16

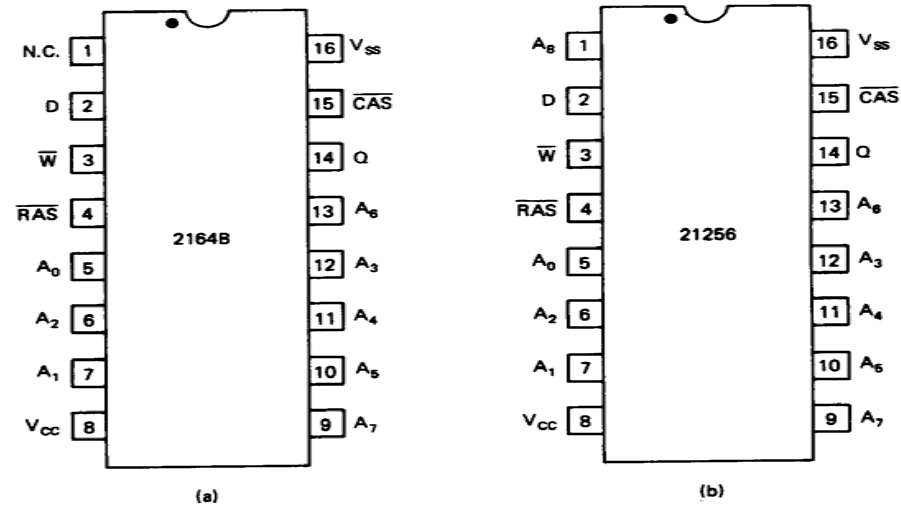


Figure 9-19 Standard DRAM devices.

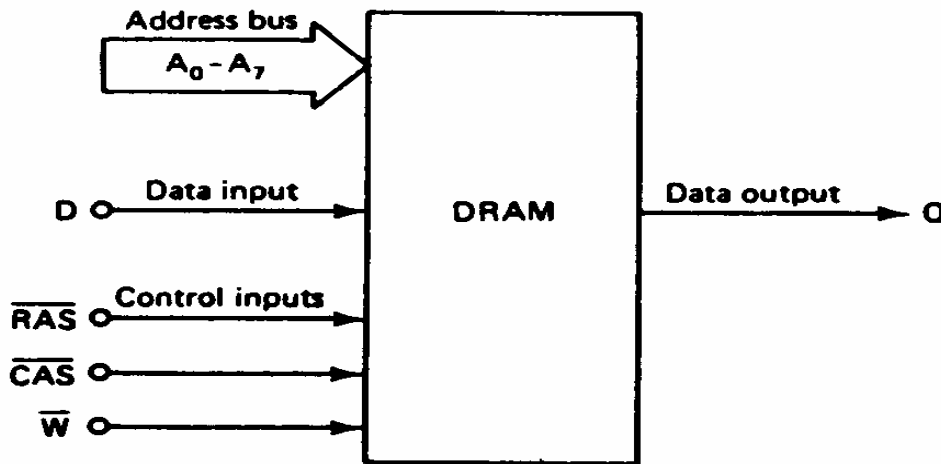


Figure 9-21 Block diagram of the 2164B DRAM.

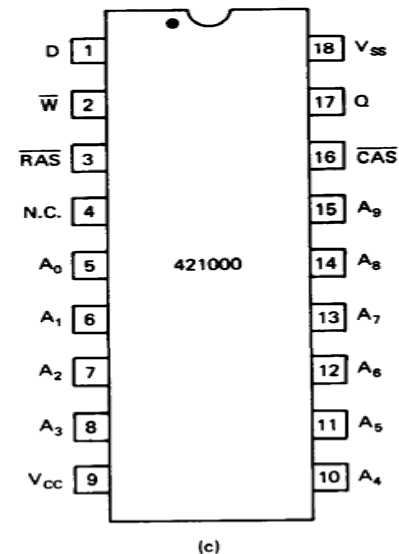
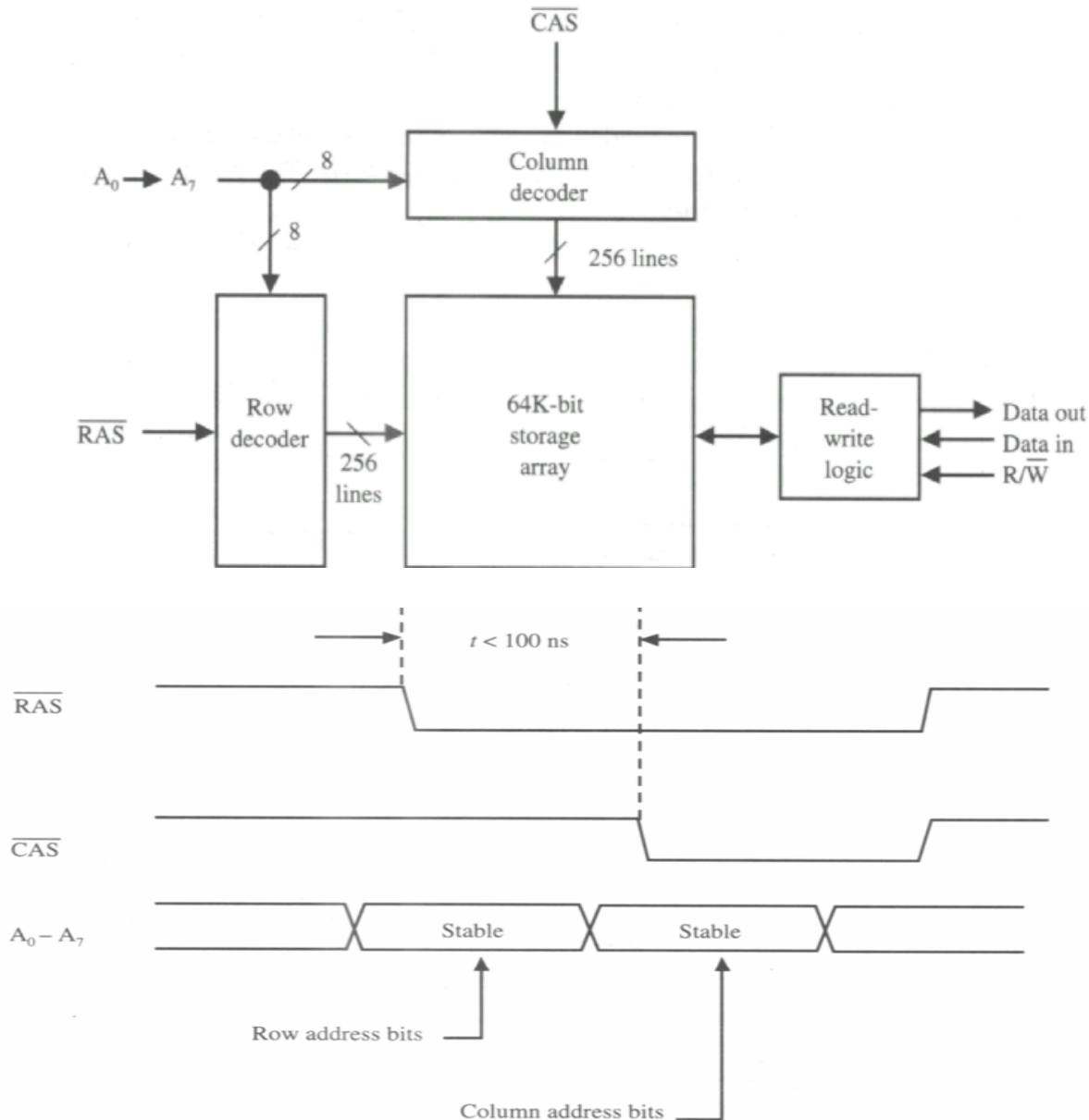


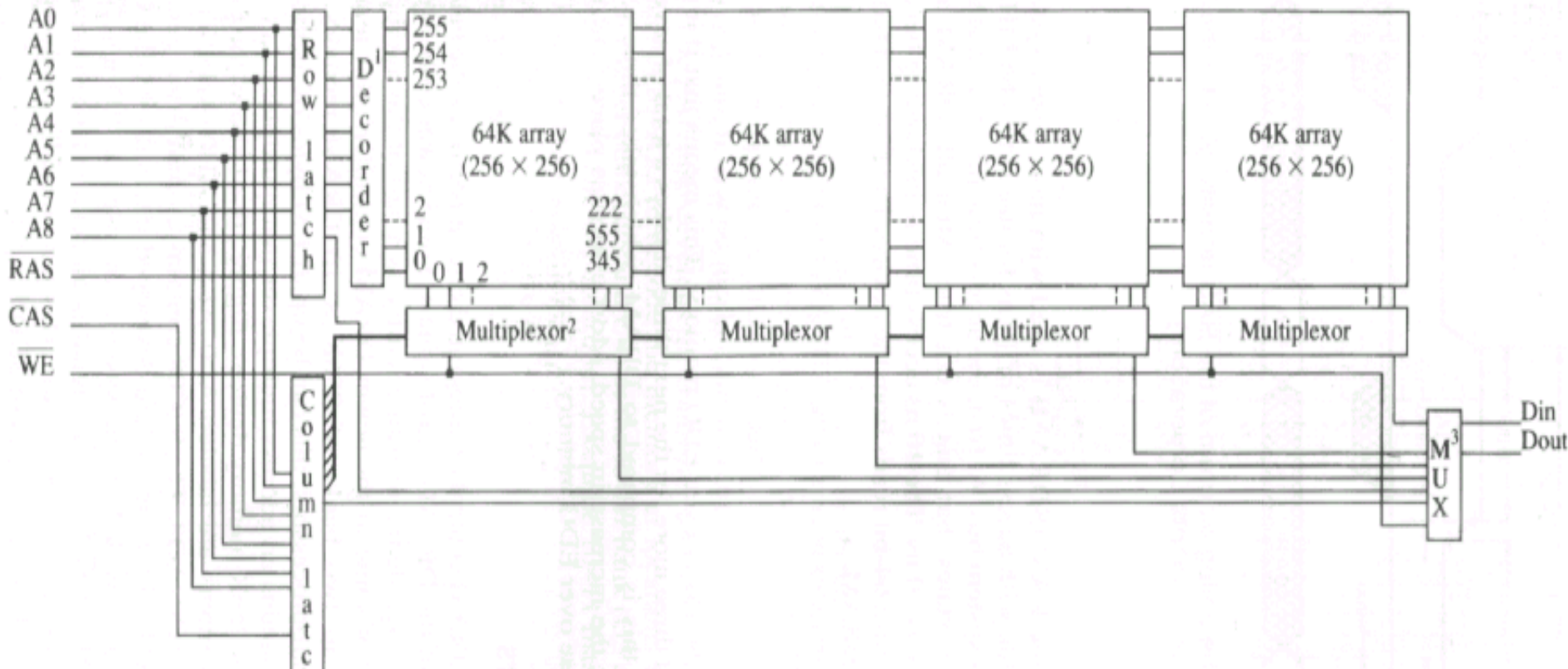
Figure 9-20 (a) 2164B pin layout. (b) 21256 pin layout. (c) 421000 pin layout.

DRAM



- In DRAM, the 8 address lines are latched accordingly by the strobe of the RAS and CAS signals.
- For example: To load a 16 bit address into the DRAM 8 bits of the address are first latched by pulling RAS low, then other 8 bits are presented to A₀-A₇ and CAS is pulled low.

DRAM Internal



Refresh time example:

For a $256K \times 1$ DRAM with 256 rows, a refresh must occur every $15.6\mu s$ ($4ms/256$).

For the 8086, a read or write occurs every $800ns$.

This allows **19** memory reads/writes per refresh or **5%** of the time.

DRAM Addressing

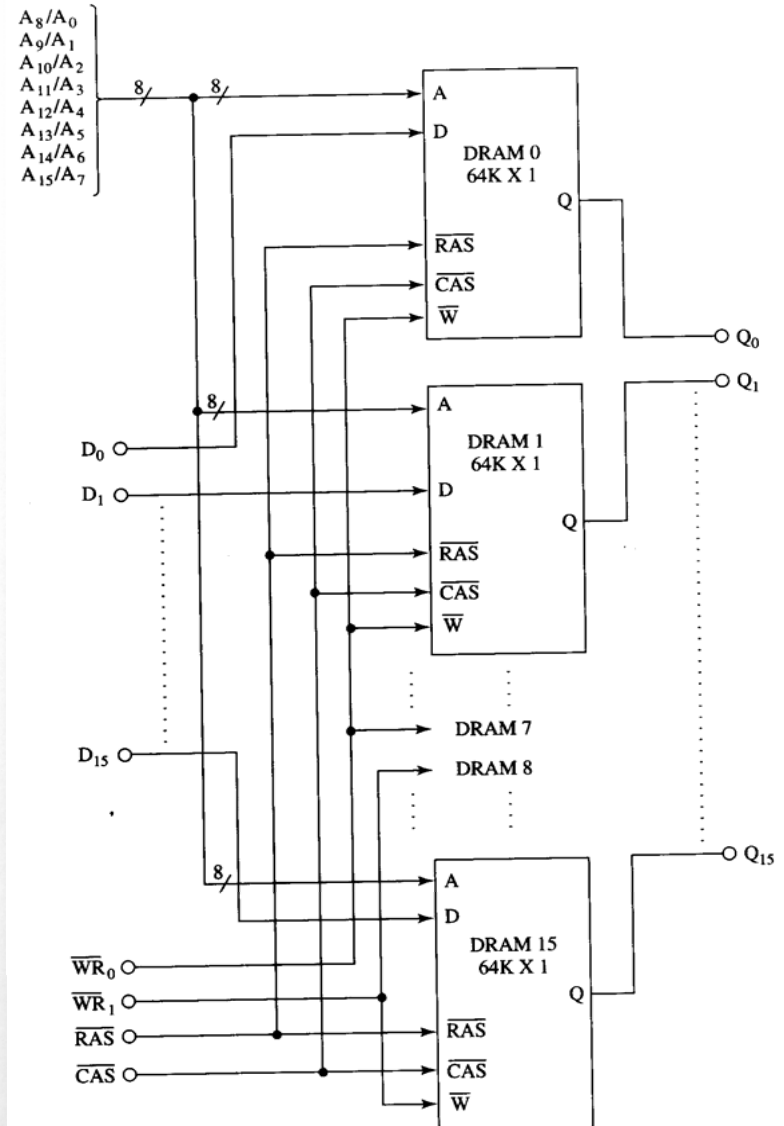
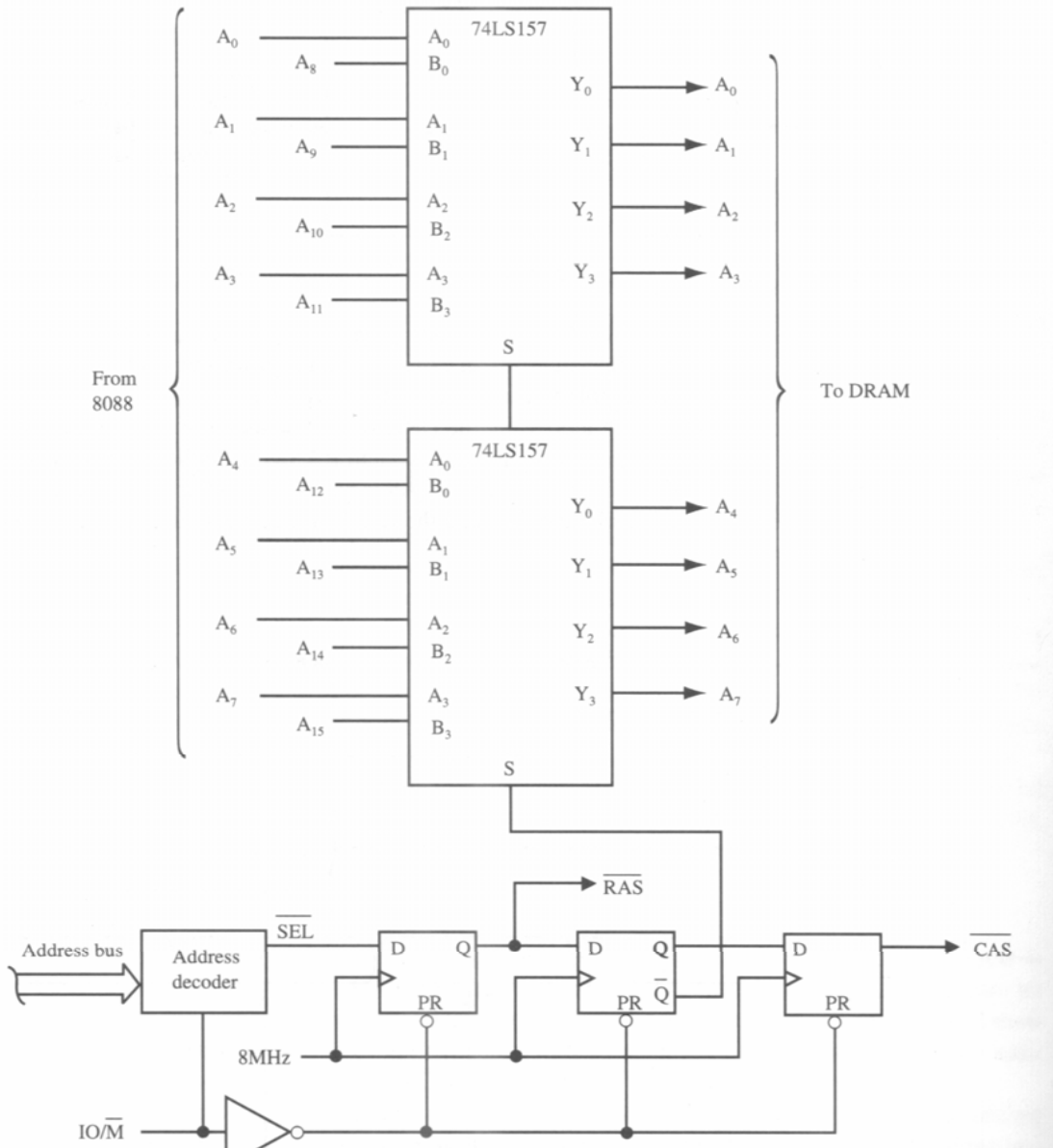
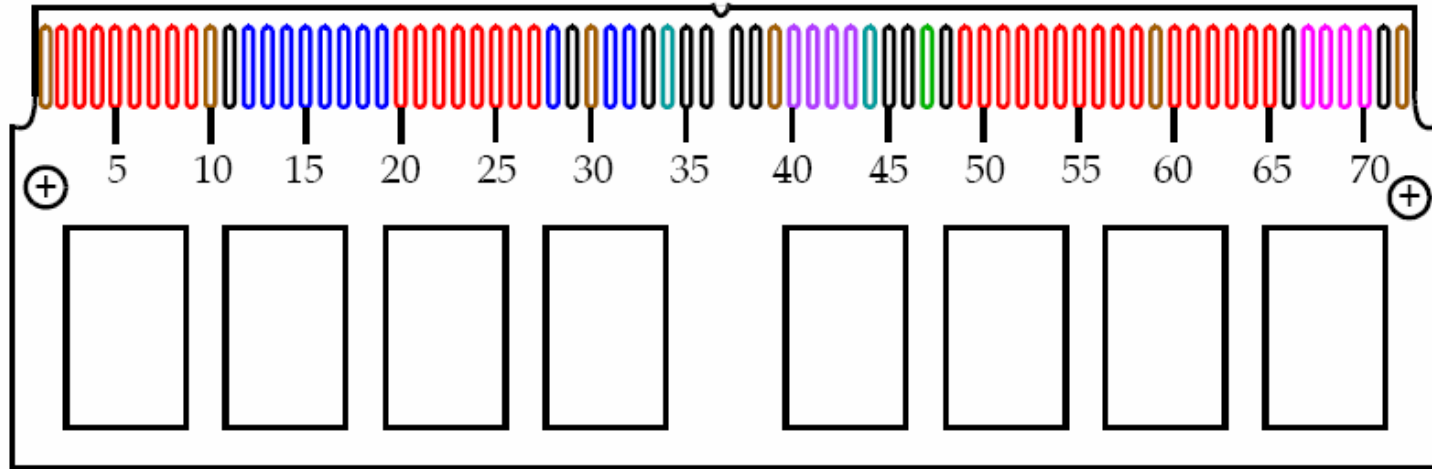


Figure 9-22 64K x 16-bit DRAM circuit.

DRAM Packaging

V_{SS} $Addr_{0-11}$ \overline{RAS} \overline{W} NC
 V_{CC} DQ_{0-31} \overline{CAS} \overline{PD}_{1-4}



Larger DRAMs are available which are organized as $1M \times 1$, $4M \times 1$, $16M \times 1$, $64M \times 1$, $256M \times 1$. DRAMs are typically placed on **SIMM (Single In-line Memory Modules)** boards.

30-pin SIMMs come in $1M \times 8$, $1M \times 9$ (parity), $4M \times 8$, $4M \times 9$.

72-pin SIMMs come in $1/2/3/8/16M \times 32$ or $1M \times 36$ (parity).

Pentiums have a 64-bit wide data bus.

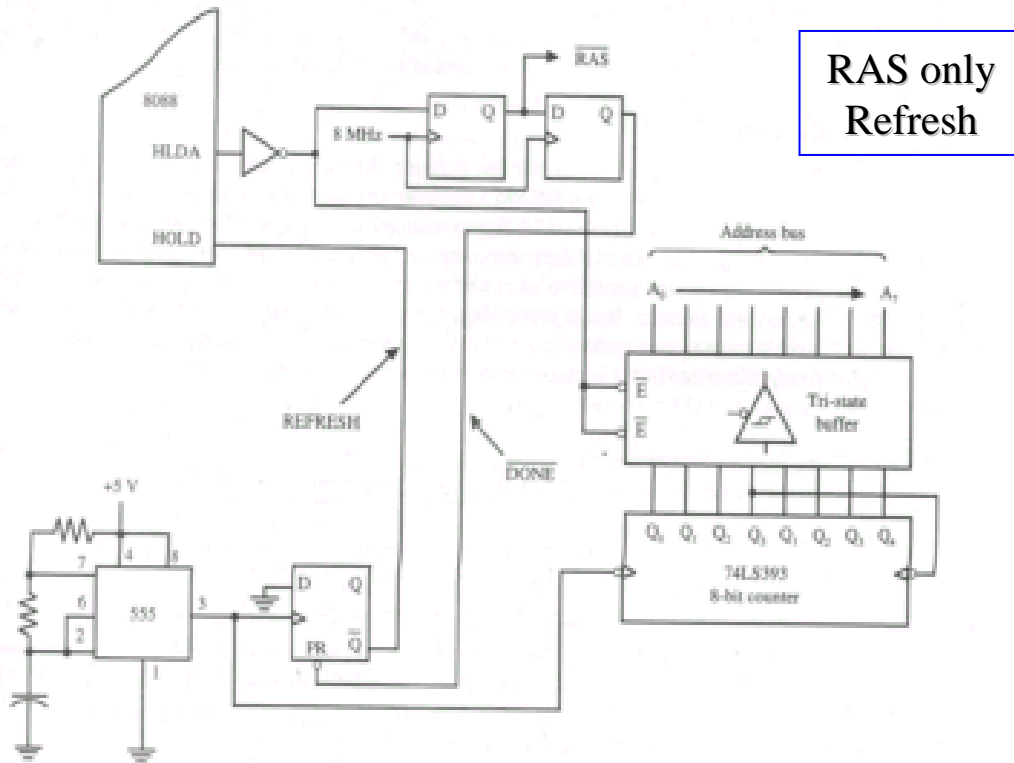
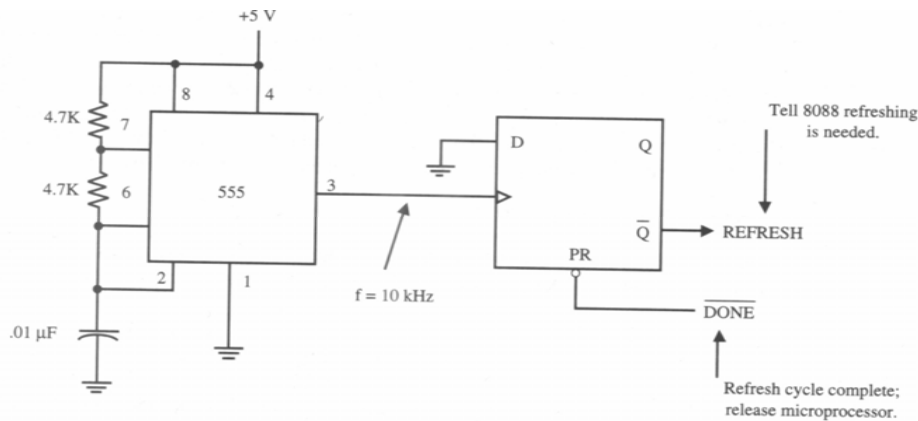
The **30-pin** and **72-pin** SIMMs are not used on these systems.

Rather, **64-bit DIMMs (Dual In-line Memory Modules)** are the standard.

These organize the memory 64-bits wide.

The board has DRAMs mounted on both sides and is **168** pins

DRAM Refresh



- DRAM can be refreshed by an external circuitry including an 8 bit counter

- HOLD/HLDA used

- Only the columns of the matrix (256 x 256 for a 64K bit matrix is needed to be refreshed.

- The refresh rate can be adjusted using a 555 timer circuitry.

DRAM in PC

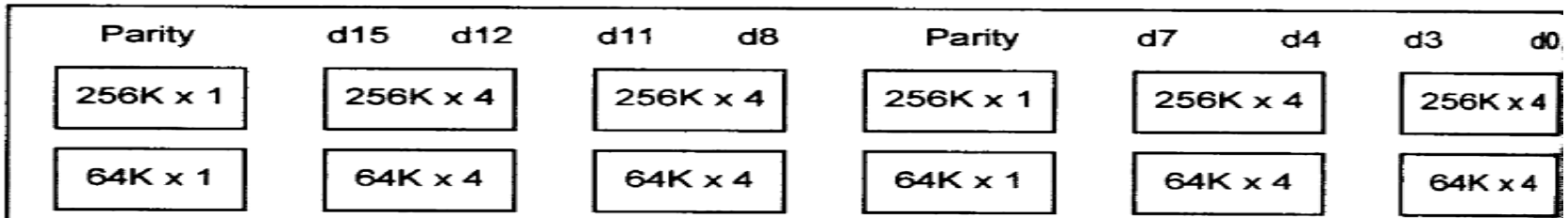


Figure 10-21. 640K Bytes of DRAM with odd and even banks designation

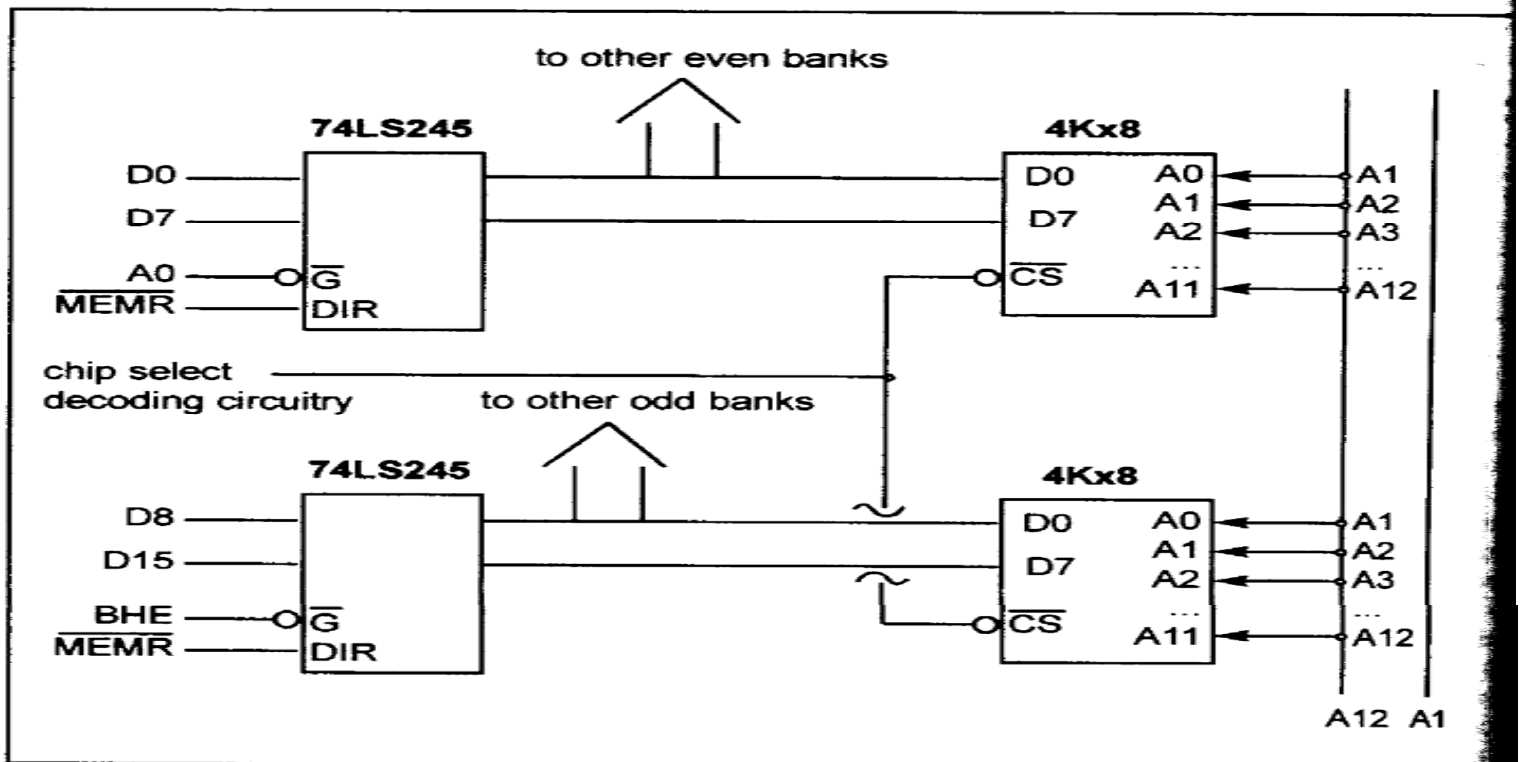


Figure 10-22. 16-bit Data Connection in the 80286 System

Parity circuits

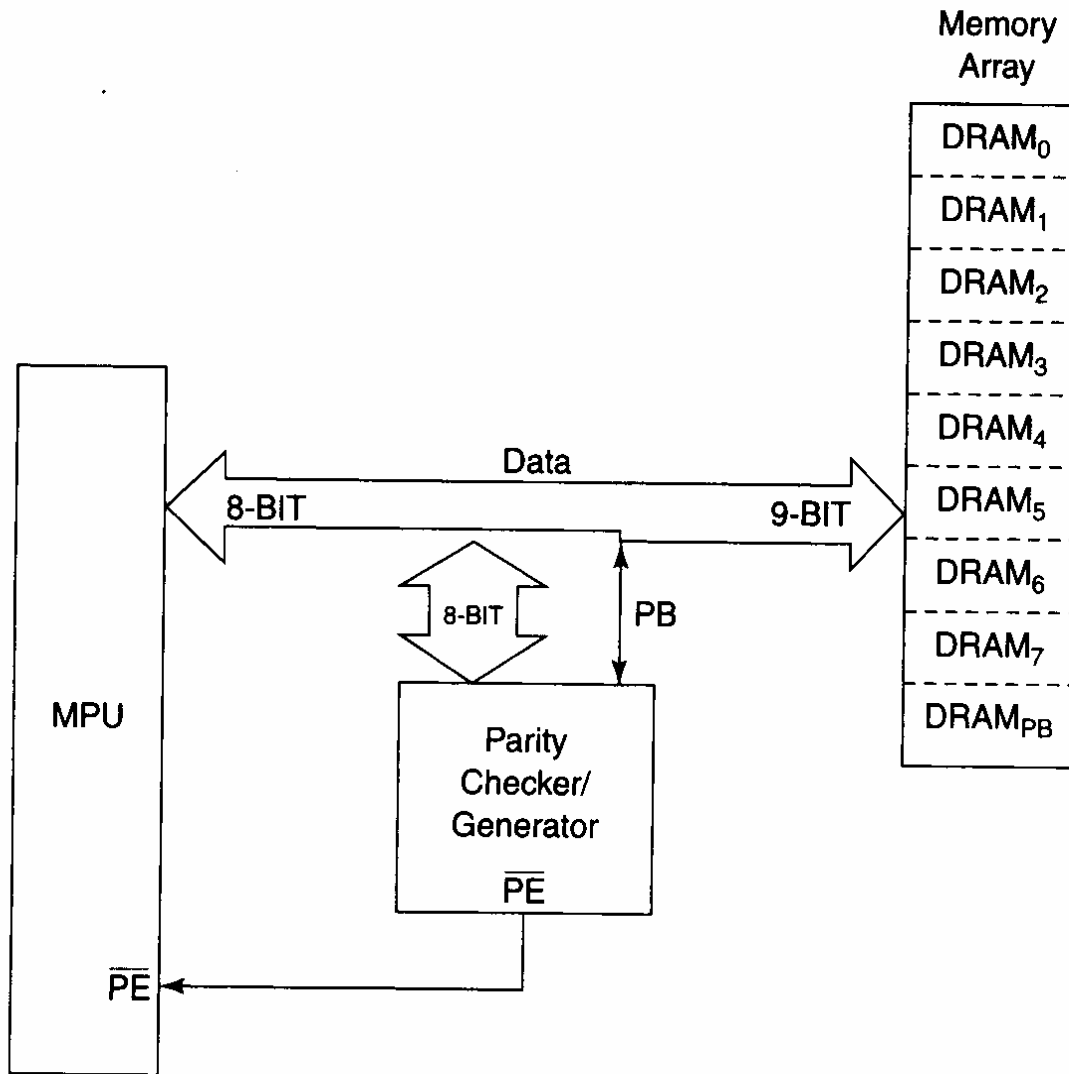


Figure 9-23 Data-storage memory interface with parity-checker generator.

Parity circuits

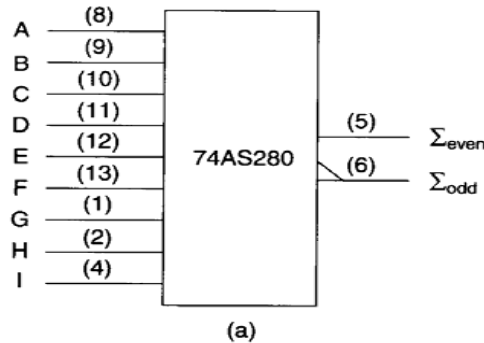
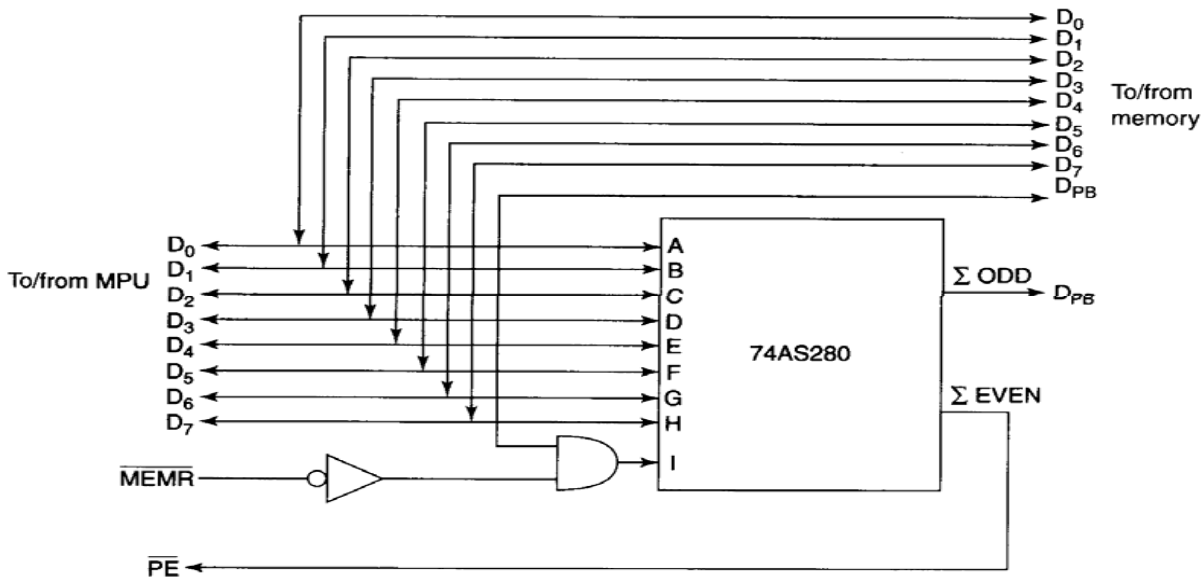


Figure 9-24 (a) Block diagram of the 74AS280. (Texas Instruments Incorporated) (b) Function table. (Texas Instruments Incorporated) (c) Even-parity checker/generator connection.

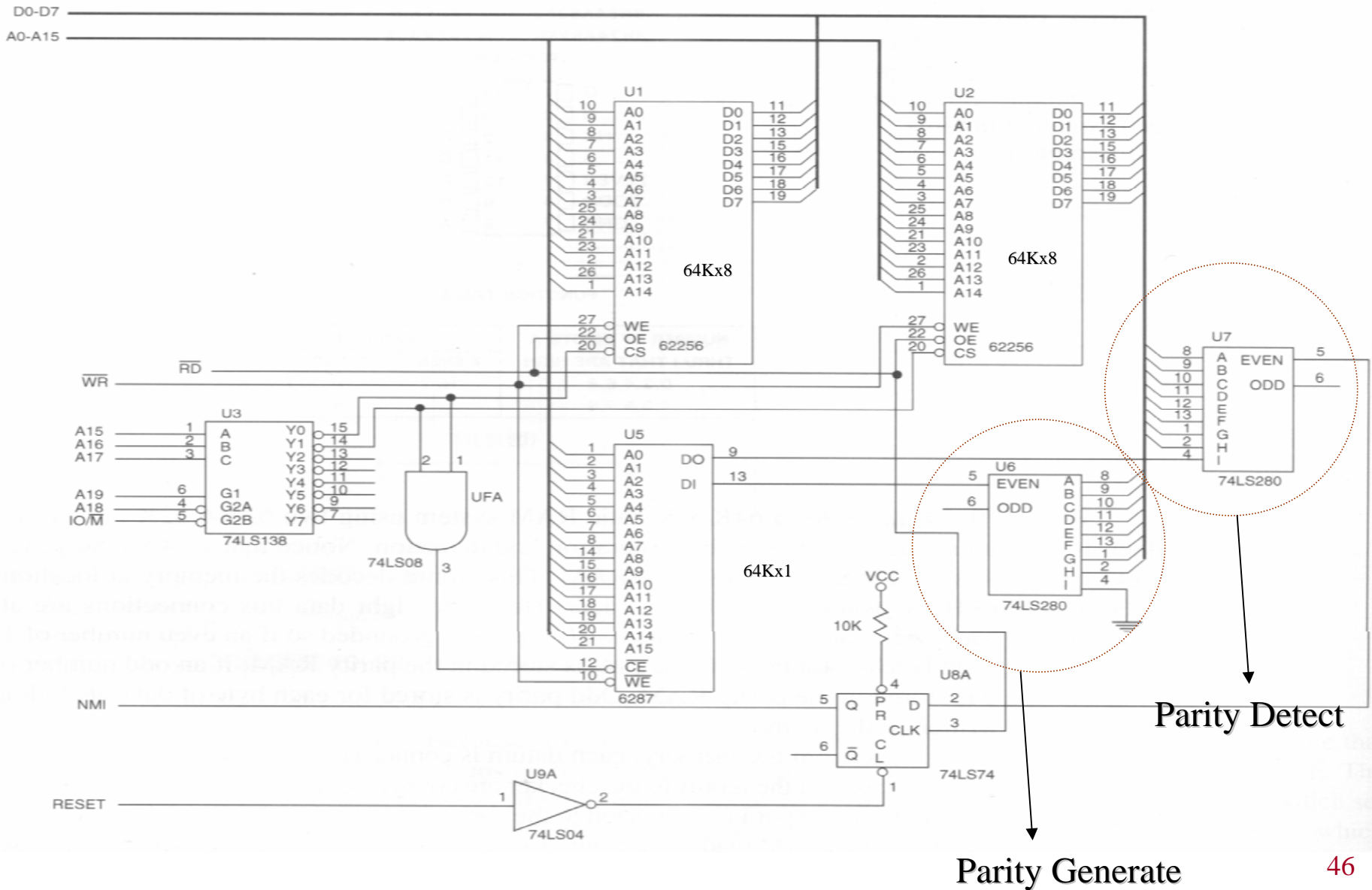
NUMBER OF INPUTS A THRU I THAT ARE HIGH	OUTPUTS	
	Σ EVEN	Σ ODD
0,2,4,6,8	H	L
1,3,5,7,9	L	H

(b)



(c)

Parity Error Detection Circuit



Checksum byte (used for ROM)

- ✓ Add the bytes together and drop the carries
- ✓ Take the 2's complement of the total sum, and that is the checksum byte, which becomes the last byte of the stored information.
- ✓ To perform the checksum operation add all the bytes, including the checksum byte. The result must be zero. If it is not zero, one or more bytes of data have been changed (corrupted)

Example: Assume that we have 5 bytes of hexadecimal data: 1A, 14, 82, FC, 3E.

- Find the checksum byte
- Perform the checksum operation to ensure integrity
- If the 3rd byte is changed to 44 show how the error is detected?

- The checksum is: $1A+14+82+FC+3E = 1EA$ drop 1 $\rightarrow EA$, take 2's comp $\Rightarrow 16$
- $1A+14+82+FC+3E+16 = 00$
- $1A+14+44+FC+3E+16 = 1C2 \rightarrow$ Error!

IBM PC Memory Map

- 00000h – 9FFFFh: RAM (640 Kb)
 - The first 1K used for the interrupt vector table (00000h to 003FFh)
 - 00400h to 004FFh is set aside for the BIOS temporary area
 - 00500h to 005FFh is set aside for the temporary storage of certain parameters in DOS and BASIC
 - A certain number of Kbytes is occupied by the operating system itself
- A0000h – BFFFFh: Video Display RAM (128 Kb)
 - A total of 128 Kbytes is allocated for video
 - Of that 128K, only a portion is used for VDR, the amount depending on which type of video adapter card is installed in the system
- C0000h – FFFFFh: ROM (256 Kb)
 - 256 K is set aside for ROM
 - Used in
 - BIOS ROM, Basic language compiler ROM, hard disk controller, other peripheral board ROMS and the rest for expansion by the user

IBM PC Memory Map

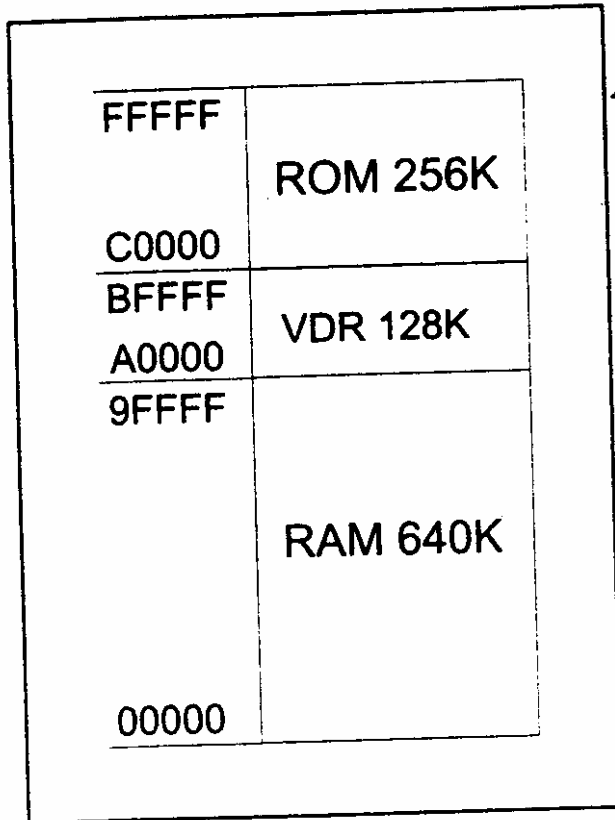


Figure 11-6. Memory Map of the IBM PC

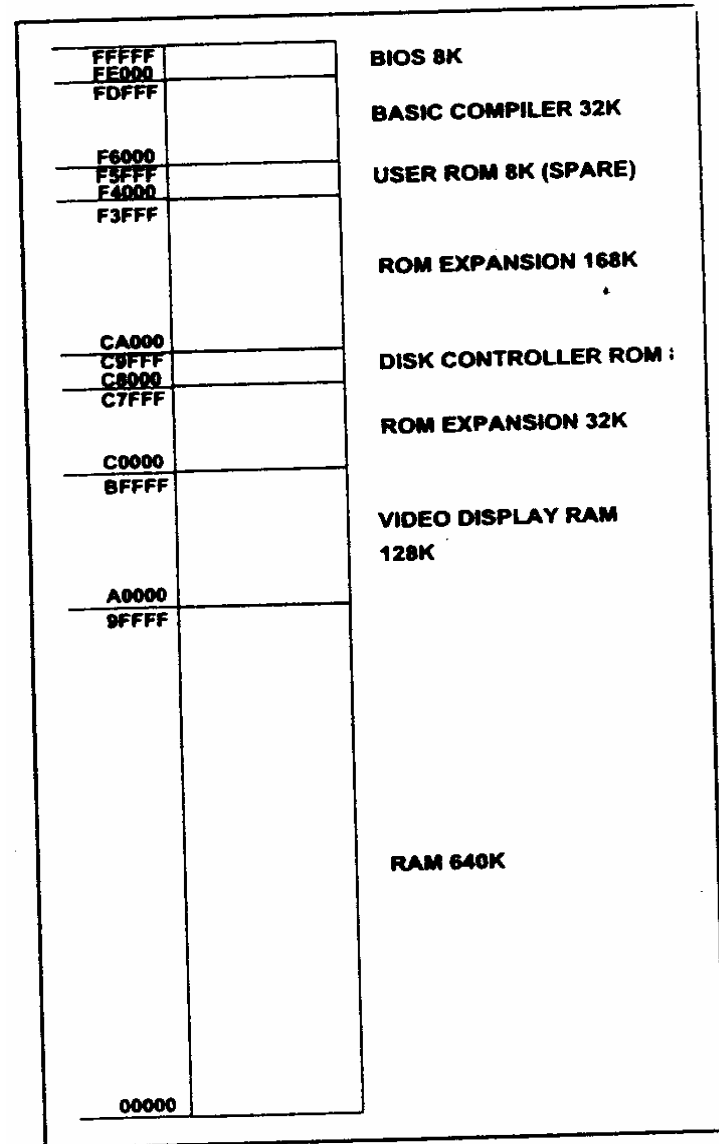


Figure 11-8. PC.XT Detailed Memory Map

IBM PC Memory Map

Table 11-5: System Identification Byte for Some IBM Products

Product	BIOS Date	Model
PC	04/24/81	FF
PC	10/19/81	FF
PC	10/27/82	FF
PC XT	11/08/82	FE
PC XT	01/10/86	FB
PC XT	05/09/86	FB
PC jr	06/01/83	FD
AT	01/10/84	FC
AT	06/10/85	FC
AT	11/15/85	FC
PC XT Model 286	04/21/86	FC
PC Convertible	09/13/85	F9
Personal System 2 Model 30	09/02/86	FA
Personal System 2 Model 50	*	FC
Personal System 2 Model 60	*	FC
Personal System 2 Model 80	*	F8
Personal System 2 Model 80	*	F8

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Memory Location	Description
F000:E000 - F000:E6F1	Power-On Start-Up Tests (POST)
F000:E6F2 - F000:E728	Boot strap loader (INT 19H)
F000:E729 - F000:E82D	RS-232 I/O (INT 14H)
F000:E82E - F000:E881	Keyboard I/O (INT 16H)
F000:E882 - F000:E986	Keyboard scan code tables
F000:E987 - F000:EC58	Keyboard (INT 9H)
F000:EC59 - F000:EFD1	Diskette I/O (INT 13H)
F000:EFD2 - F000:F044	Printer I/O (INT 17H)
F000:F045 - F000:F840	Video I/O (INT 10H)
F000:F841 - F000:F84C	Memory check (INT 12H)
F000:F84D - F000:F85B	Equipment check (INT 11H)
F000:F85C - F000:FA6D	Cassette I/O (INT 15H) - not used on XT
F000:FA6E - F000:FE6D	Graphics character table
F000:FE6E - F000:FEF2	Time of day (INT 1AH)
F000:FEF3 - F000:FF52	Interrupt vector table
F000:FF53 - F000:FF53	Dummy return point for unused interrupts
F000:FF54 - F000:FFD9	Print screen (INT 5H)
F000:FFF0 - F000:FFF4	First code executed after power-on
F000:FFF5 - F000:FFFF	BIOS release date

Figure 11-11. PC/XT BIOS ROM Memory Map